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Furukawa

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(54) **SOLID ELECTROLYTIC CAPACITOR**

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 127 days.

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H01G 9/012 (2006.01)

H01G 9/048 (2006.01)

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(2013.01); **H01G 9/048** (2013.01); **H01G 9/08**

(2013.01);

(Continued)

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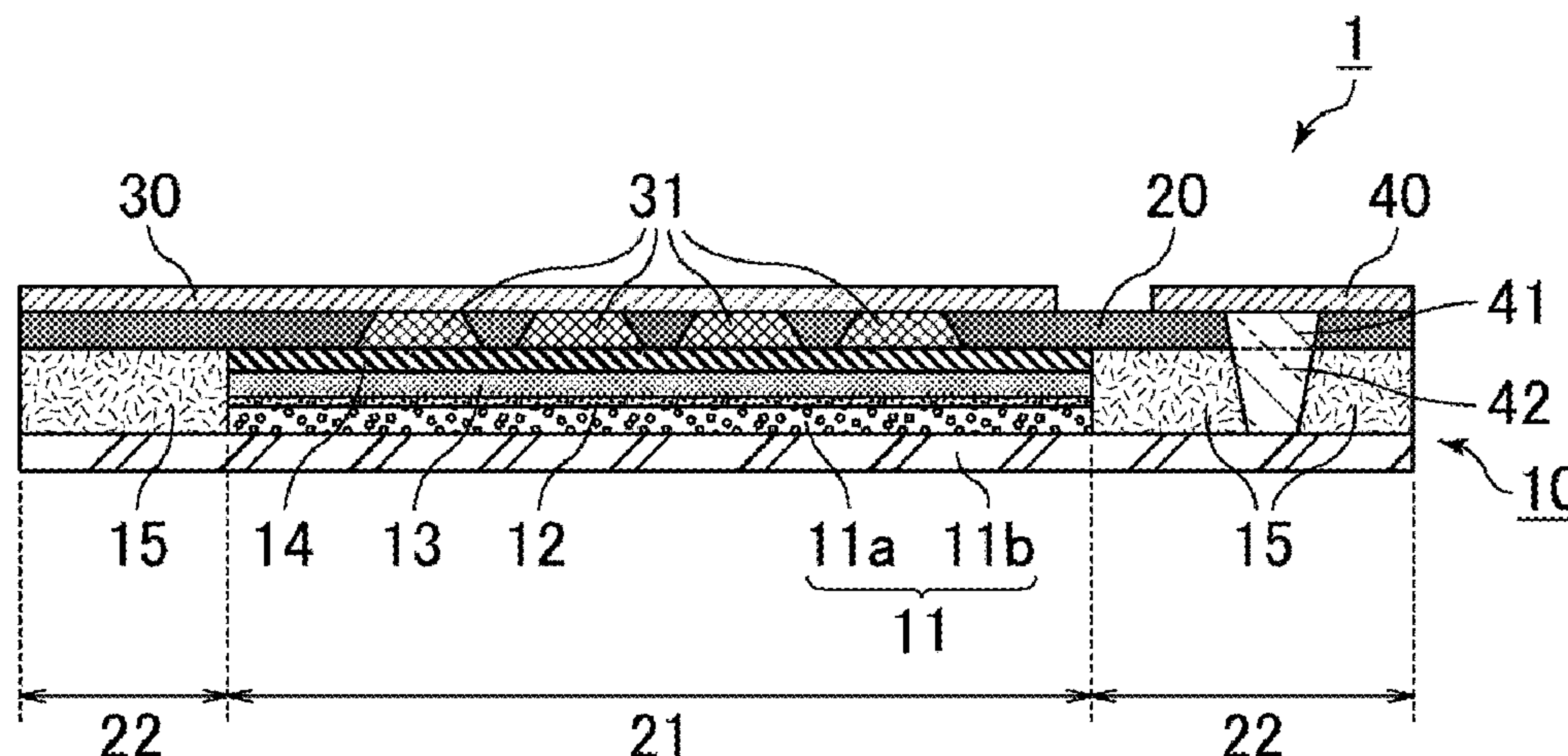
CPC H01G 9/012; H01G 9/08; H01G 9/15

See application file for complete search history.

(57) **ABSTRACT**

A solid electrolytic capacitor includes a valve-acting metal substrate including a core part and a porous part disposed on at least one principal surface of the core part. A dielectric layer is formed in a surface of the porous part and a solid electrolyte layer is disposed on the dielectric layer. A conductive layer is disposed on the solid electrolyte layer and a sealing resin seals a principal surface of the capacitor element. A cathodic outer electrode is electrically connected to the conductive layer and an anodic outer electrode is electrically connected to the core part. An insulating layer is interposed between the core part and the sealing resin. The insulating layer, the sealing resin, and the anodic outer electrode are disposed on and above the core part in this order. A first anodic via electrode is formed in the sealing resin disposed on the insulating layer so as to penetrate the sealing resin. A second anodic via electrode is formed in the insulating layer disposed on the core part so as to penetrate the insulating layer. The core part is electrically drawn to a surface of the sealing resin through the first and second anodic via electrodes. The first anodic via electrode exposed

(Continued)



at the surface of the sealing resin is connected to the anodic outer electrode.

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22 Claims, 6 Drawing Sheets

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H01G 9/00 (2006.01)
H01G 9/15 (2006.01)
H01G 9/08 (2006.01)
H01G 9/07 (2006.01)
H01G 9/10 (2006.01)
- (52) **U.S. Cl.**
 CPC *H01G 9/15* (2013.01); *H01G 9/07* (2013.01); *H01G 9/10* (2013.01)

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FIG. 1 (a)

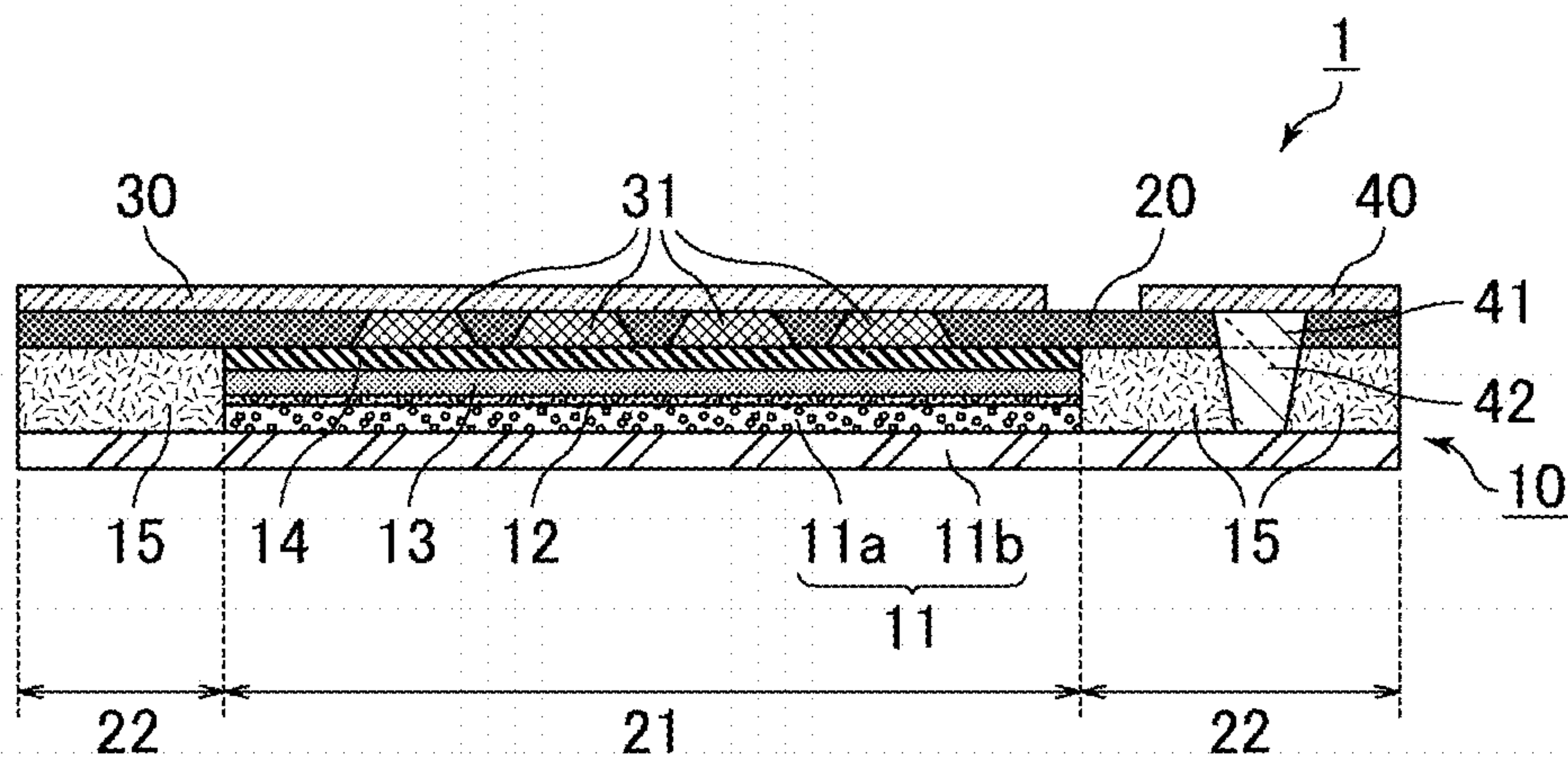


FIG. 1 (b)

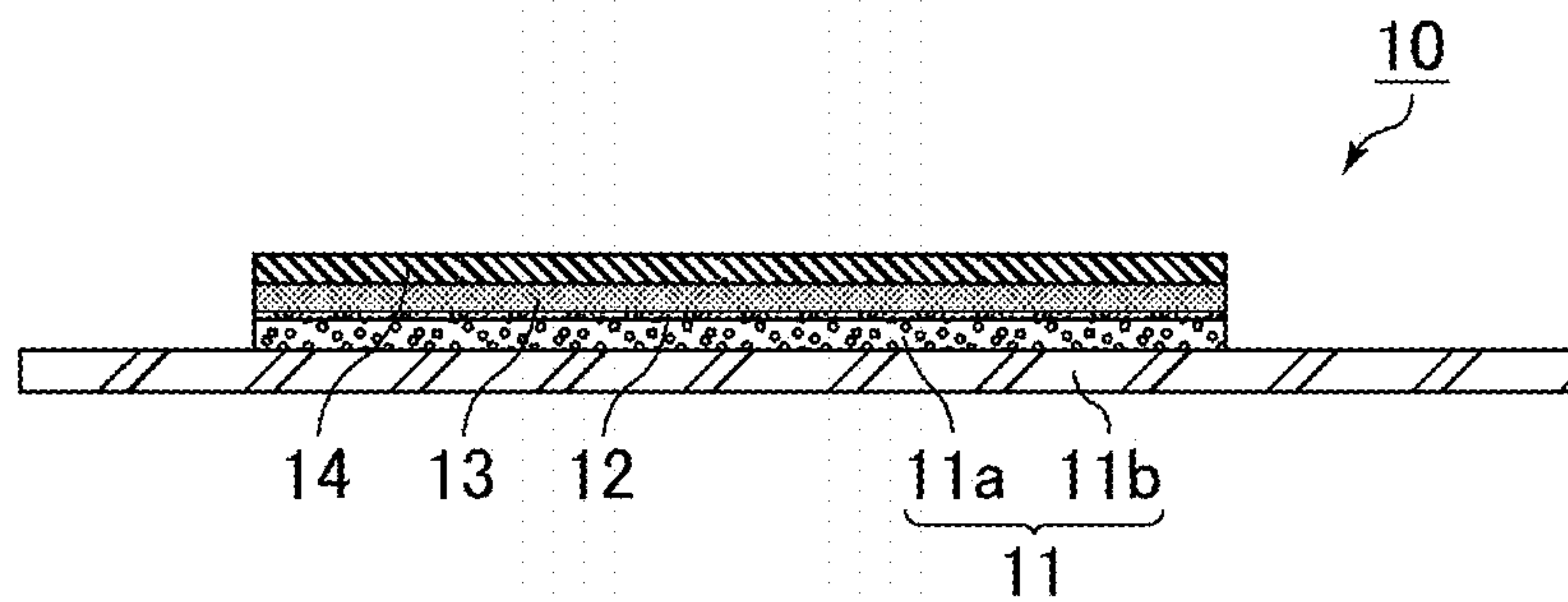


FIG. 1 (c)

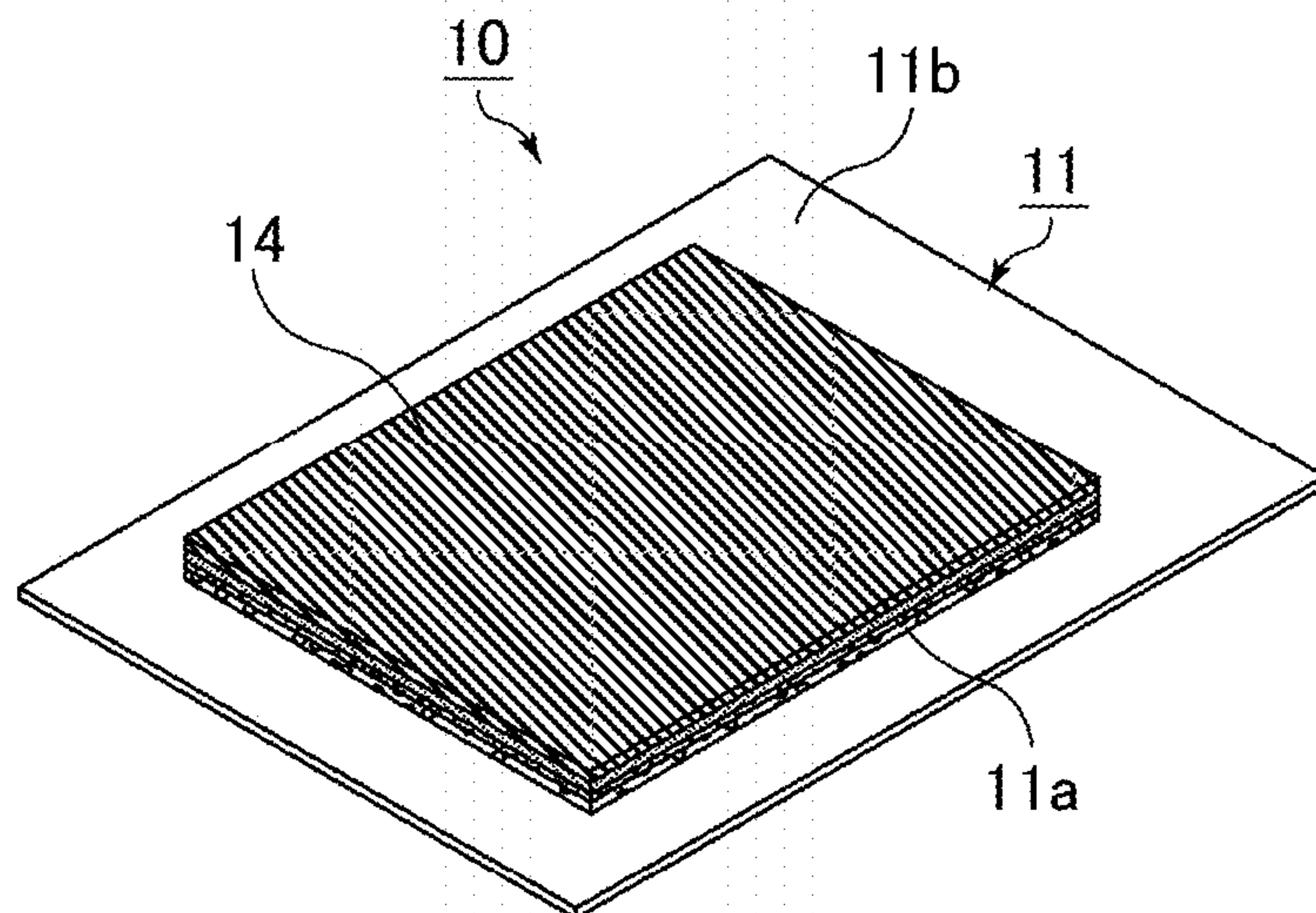


FIG. 2-1 (a)

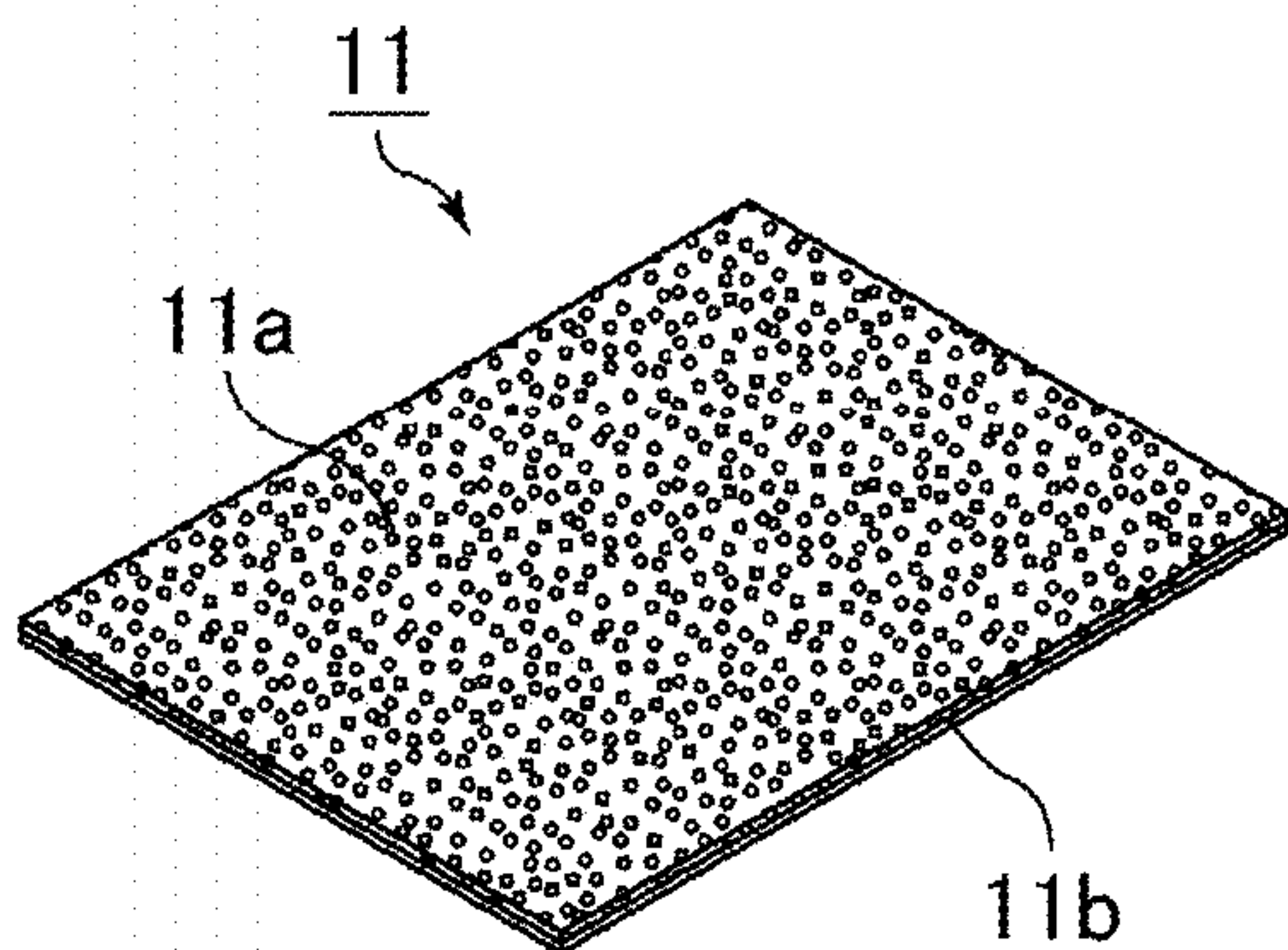


FIG. 2-1 (b)

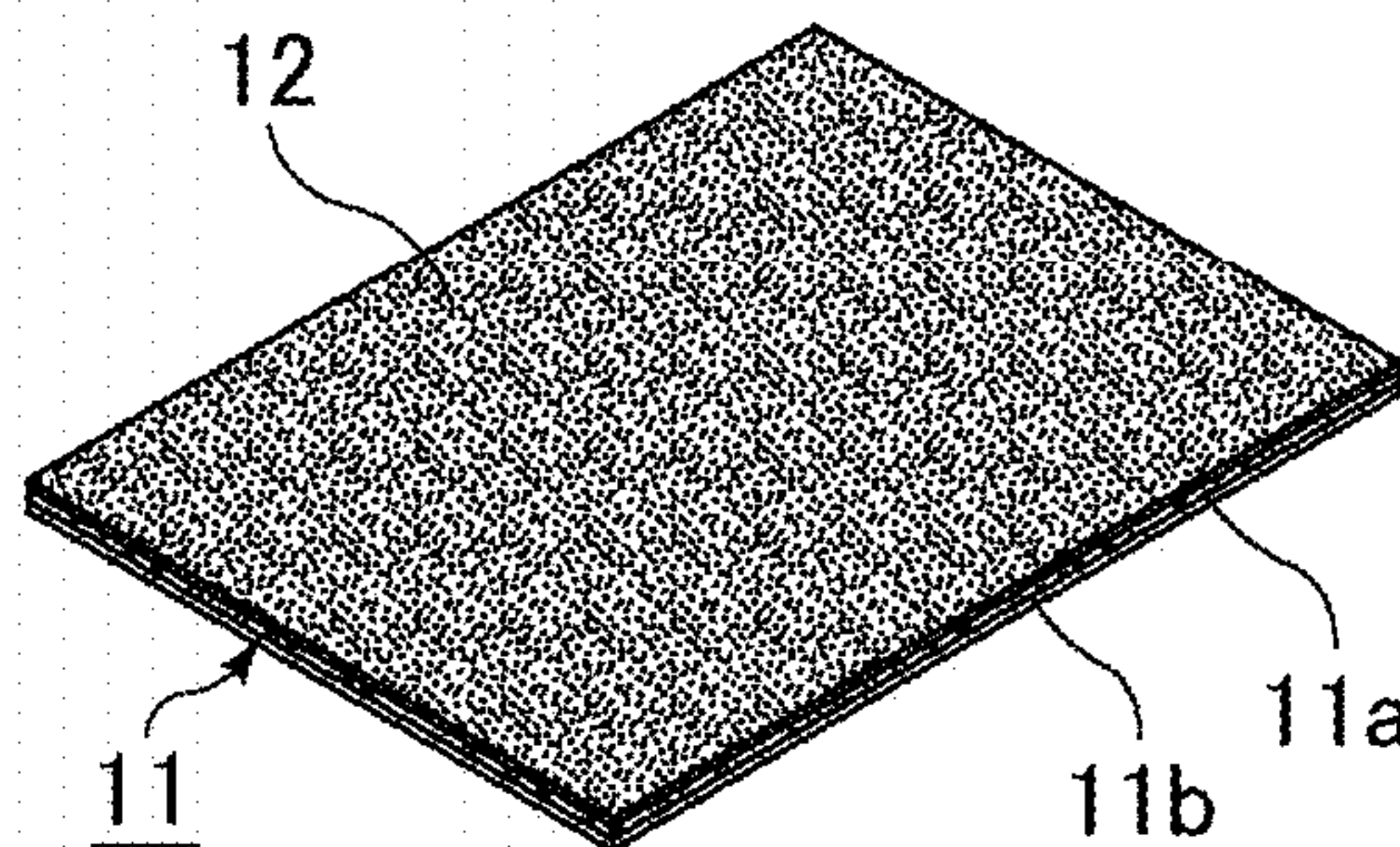


FIG. 2-1 (c)

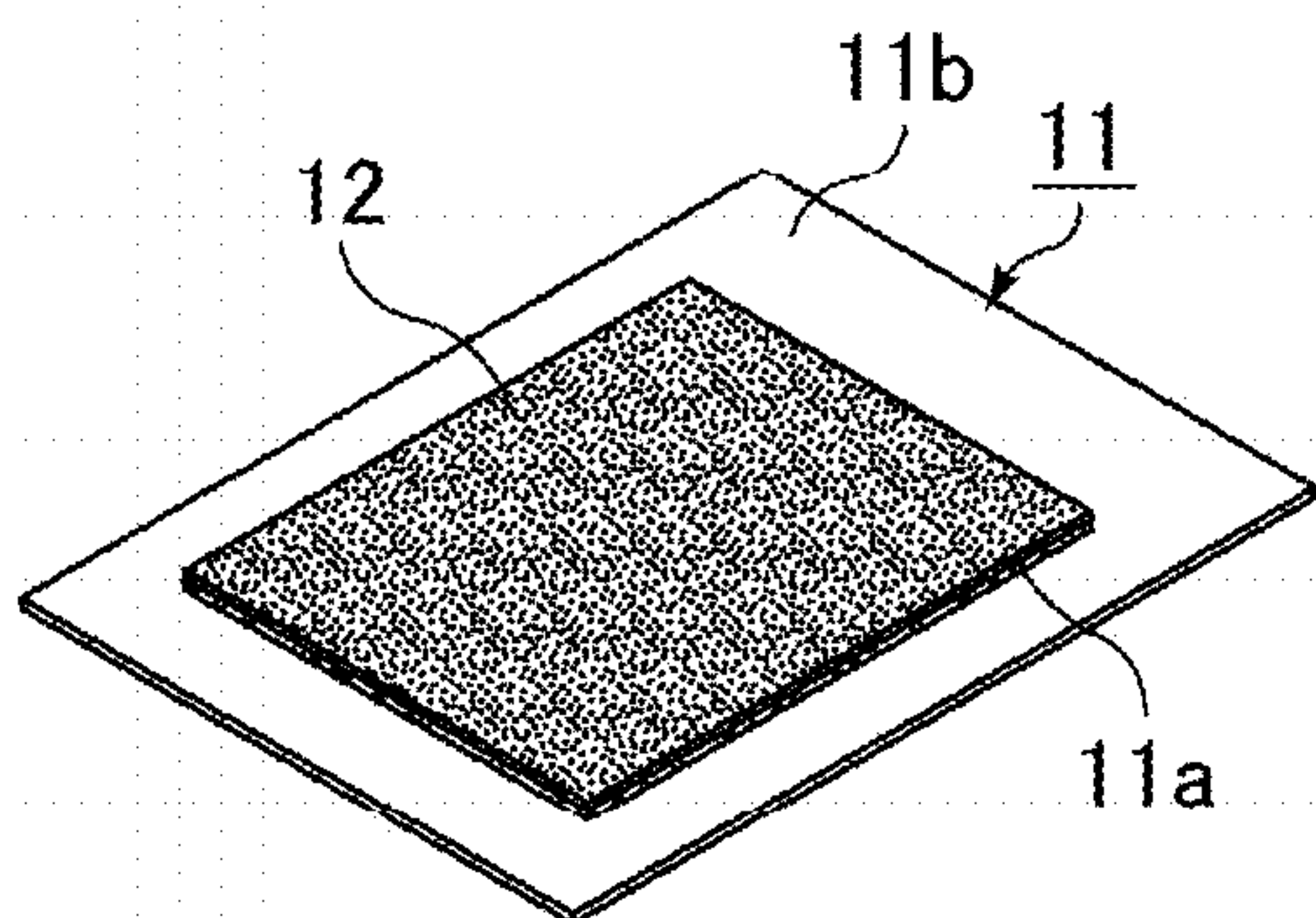


FIG. 2-1 (d)

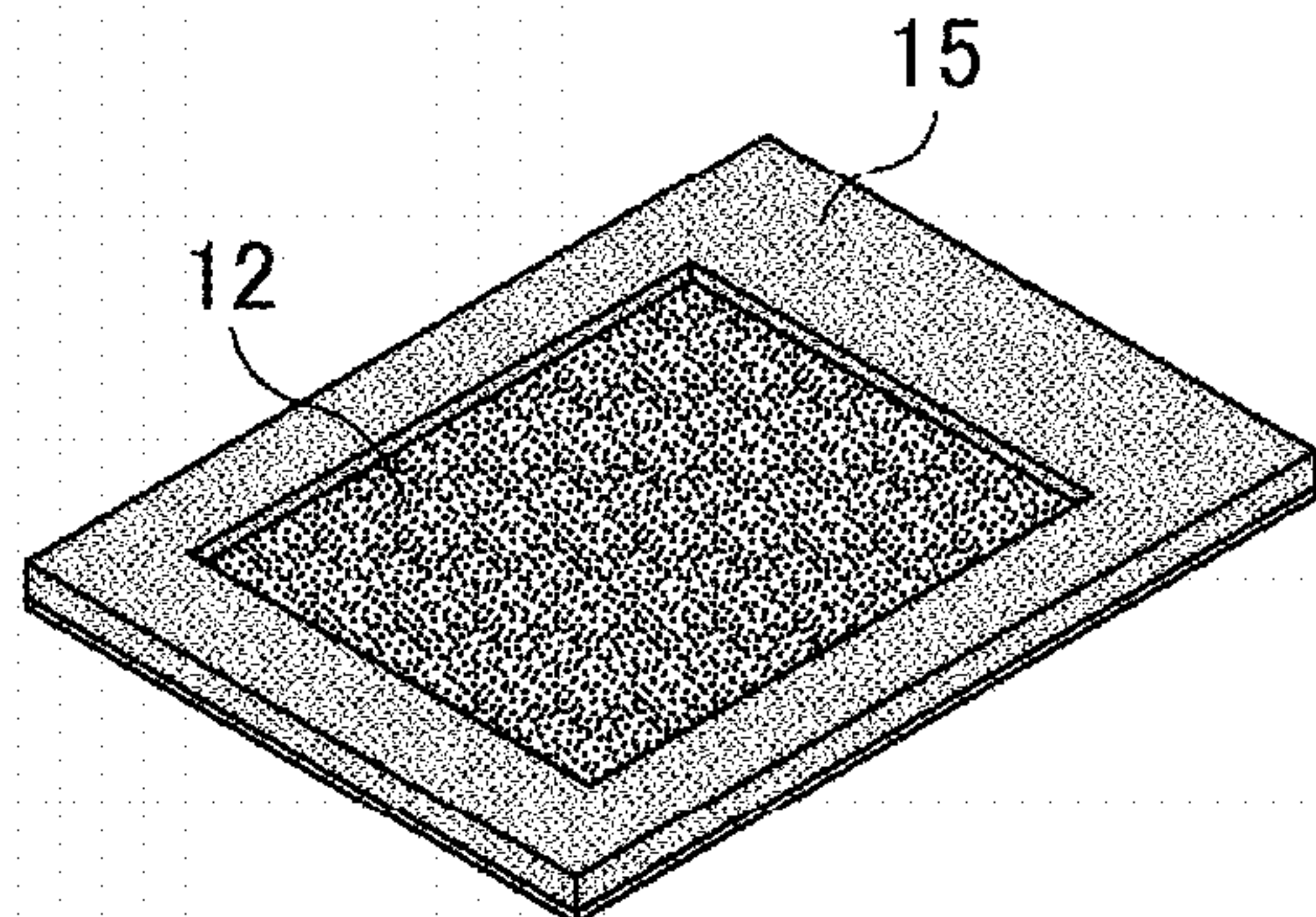


FIG. 2-1 (e)

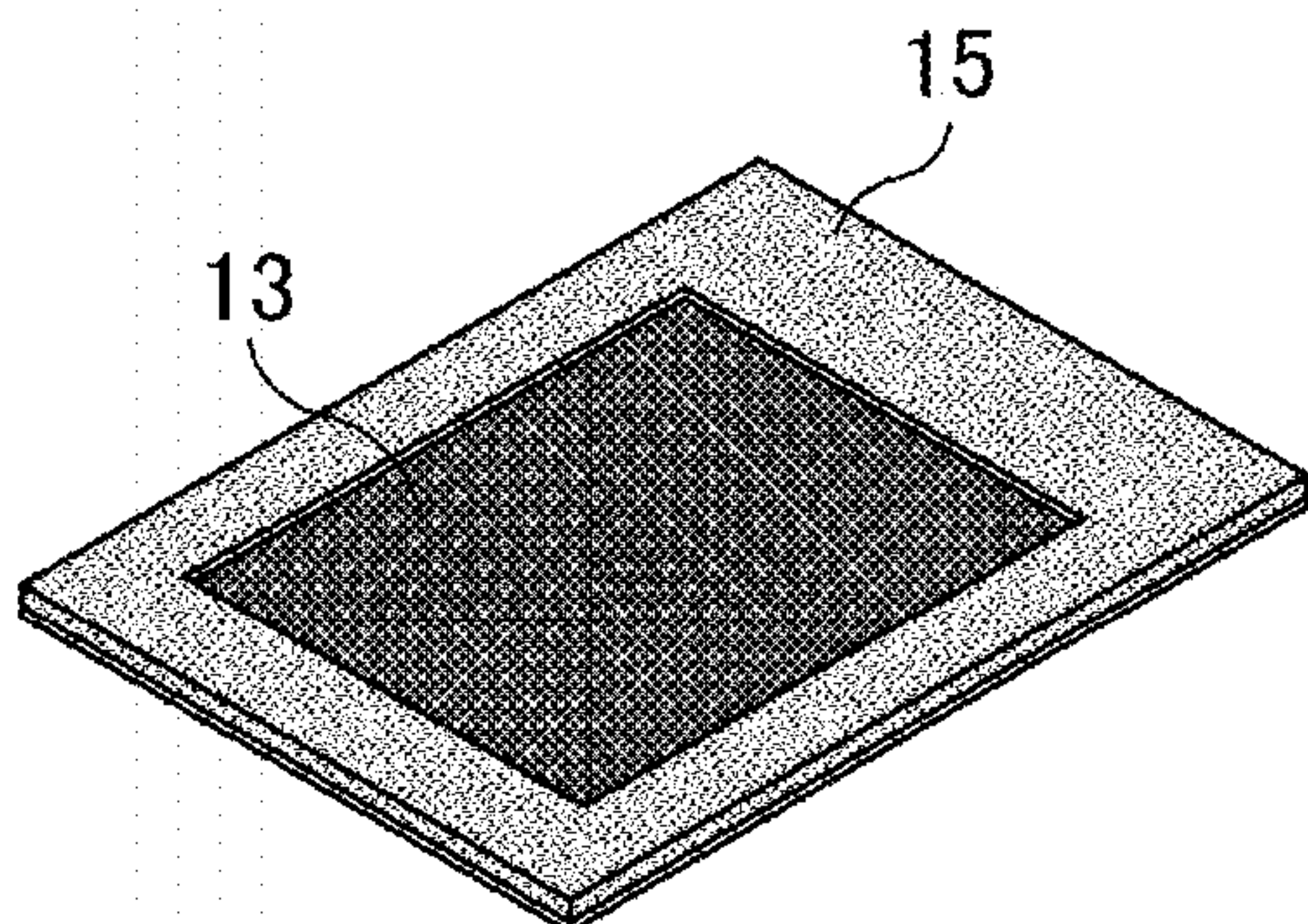


FIG. 2-1 (f)

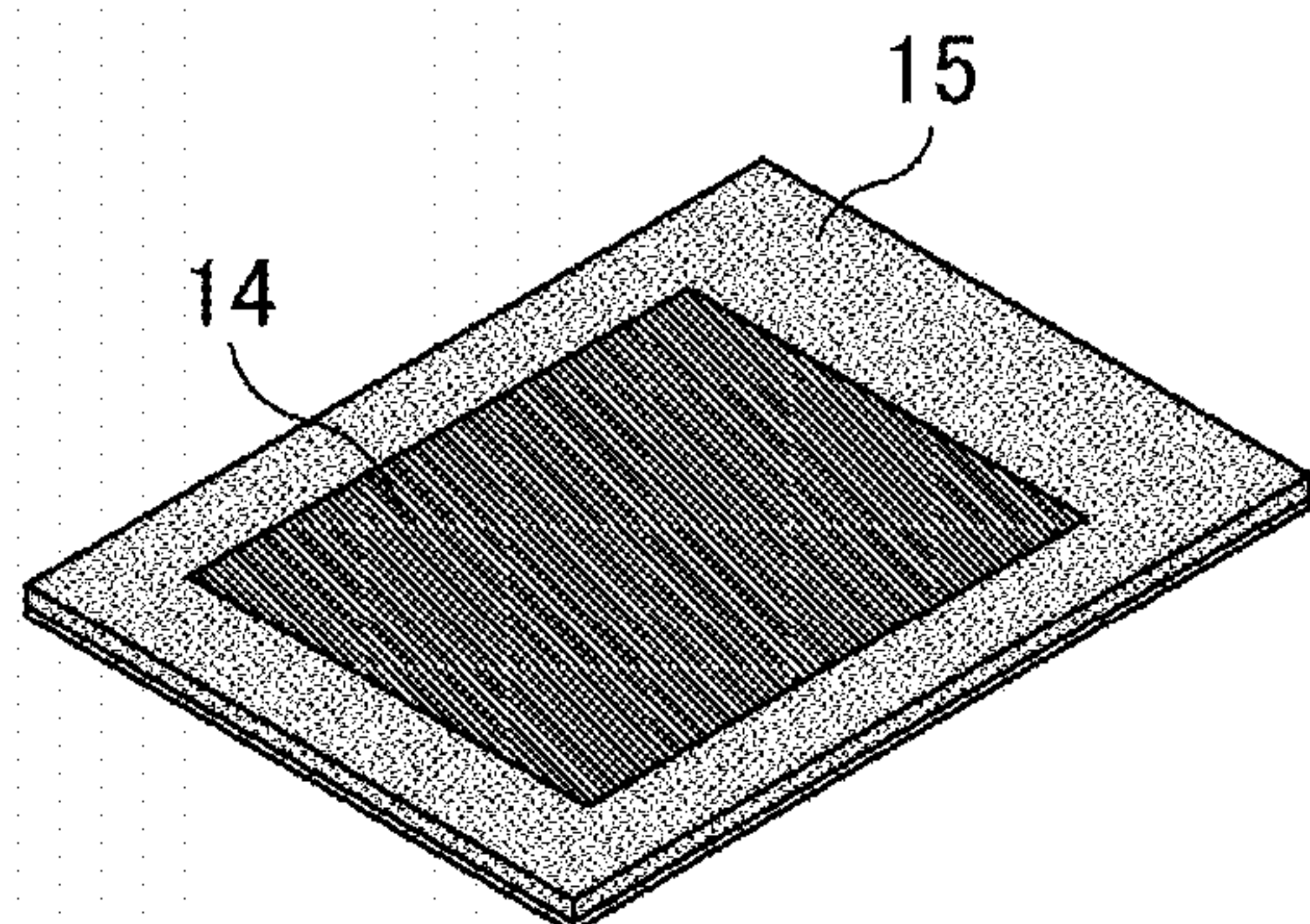


FIG. 2-2 (g)

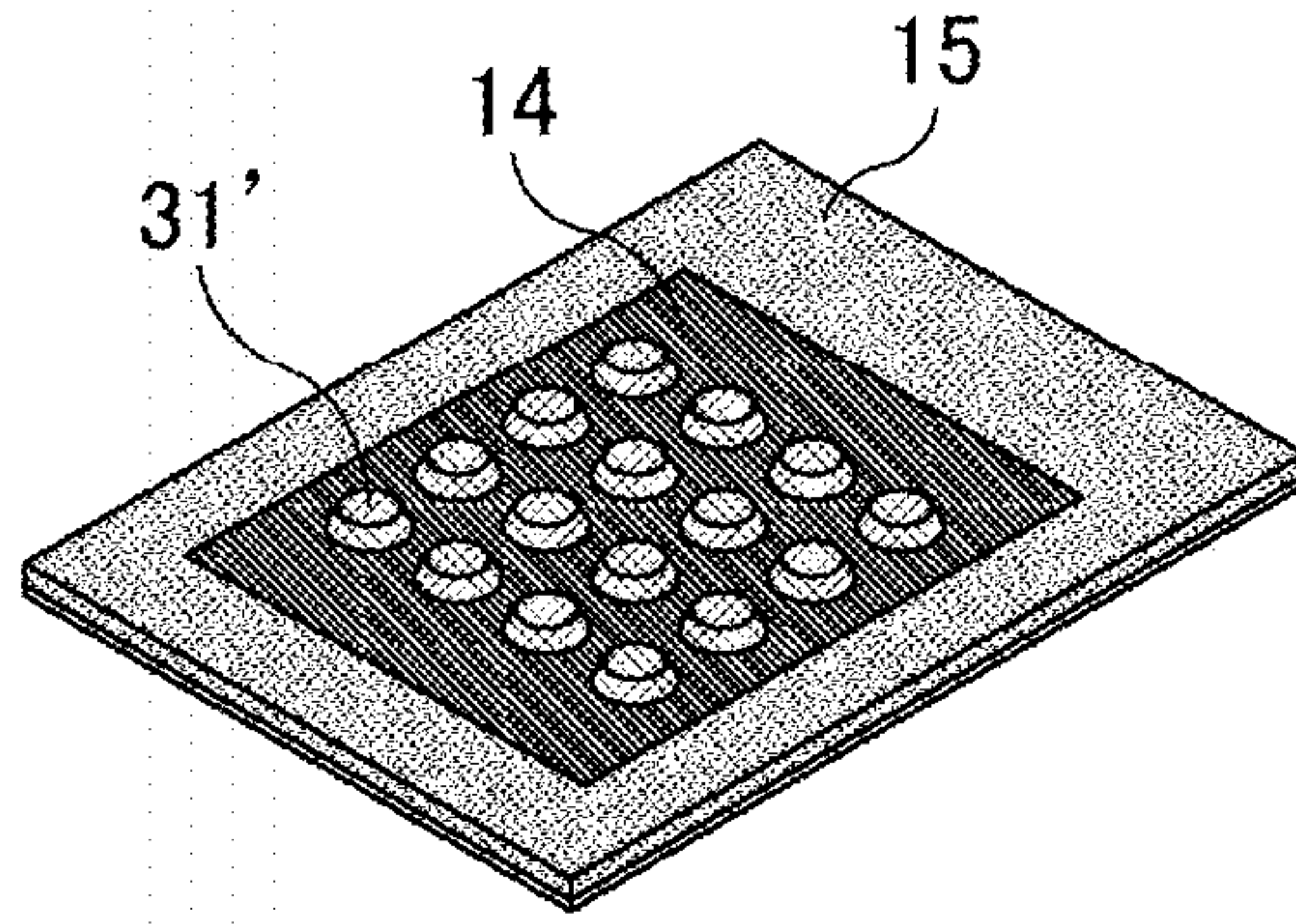


FIG. 2-2 (h)

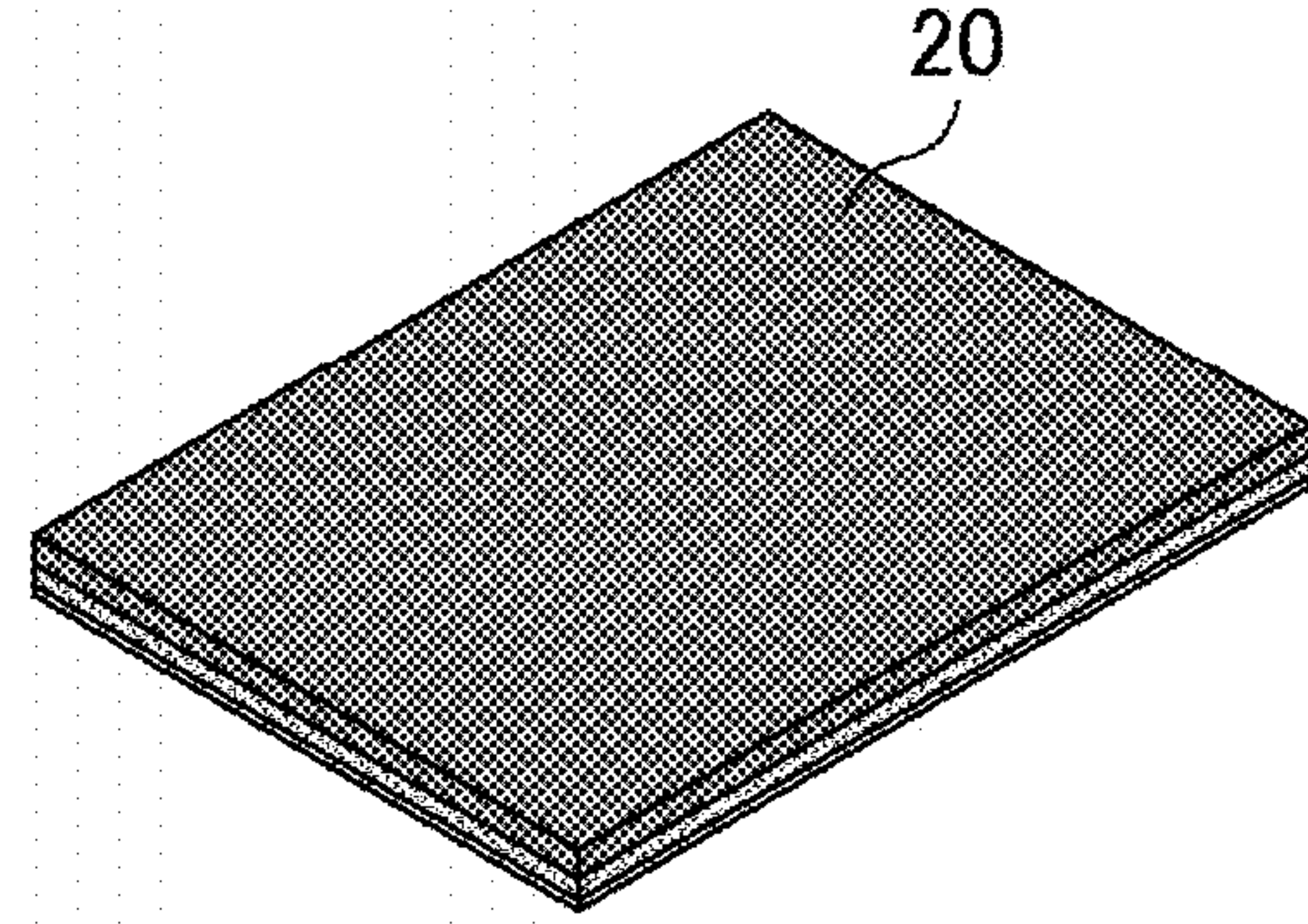


FIG. 2-2 (i)

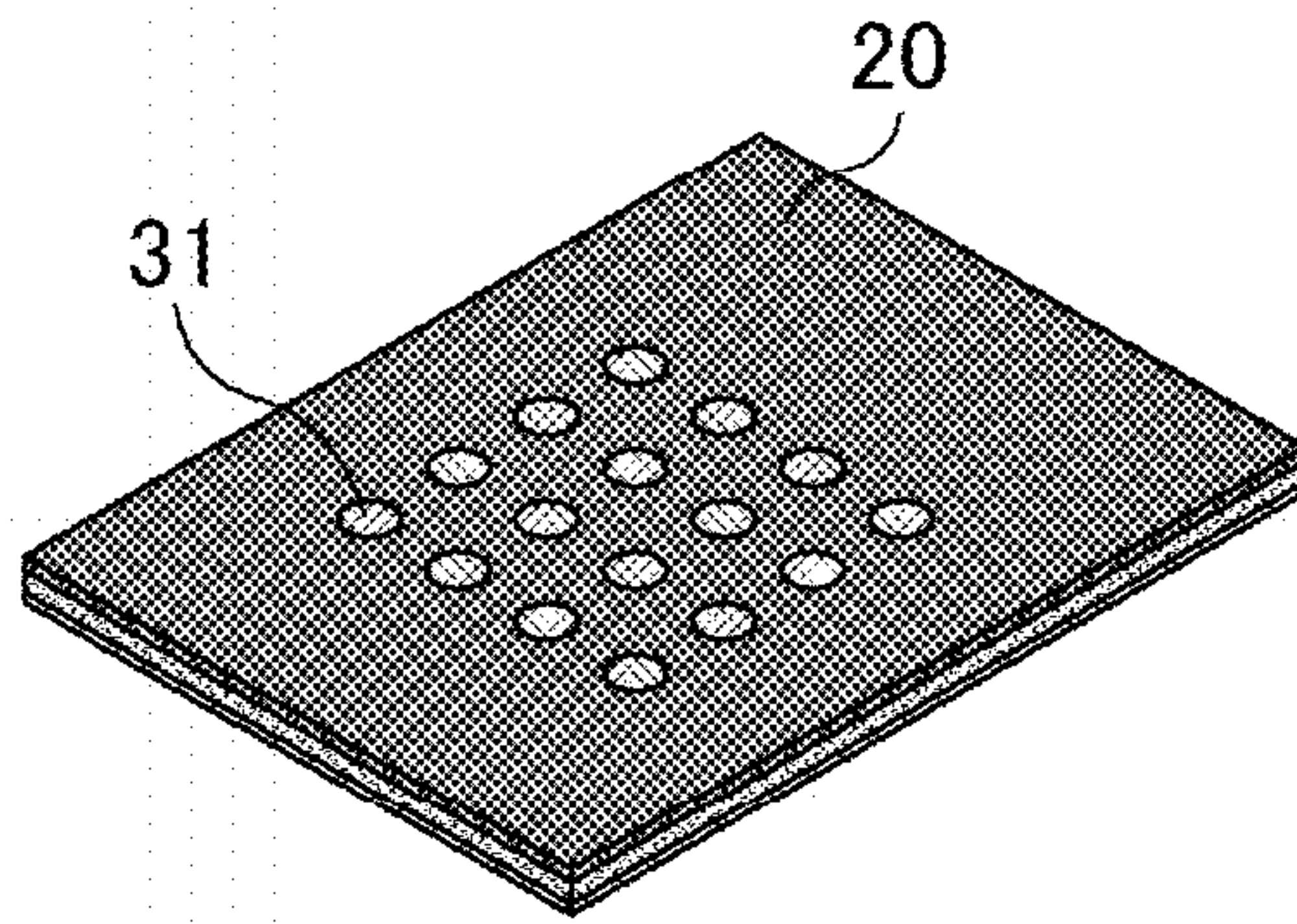


FIG. 2-2 (j)

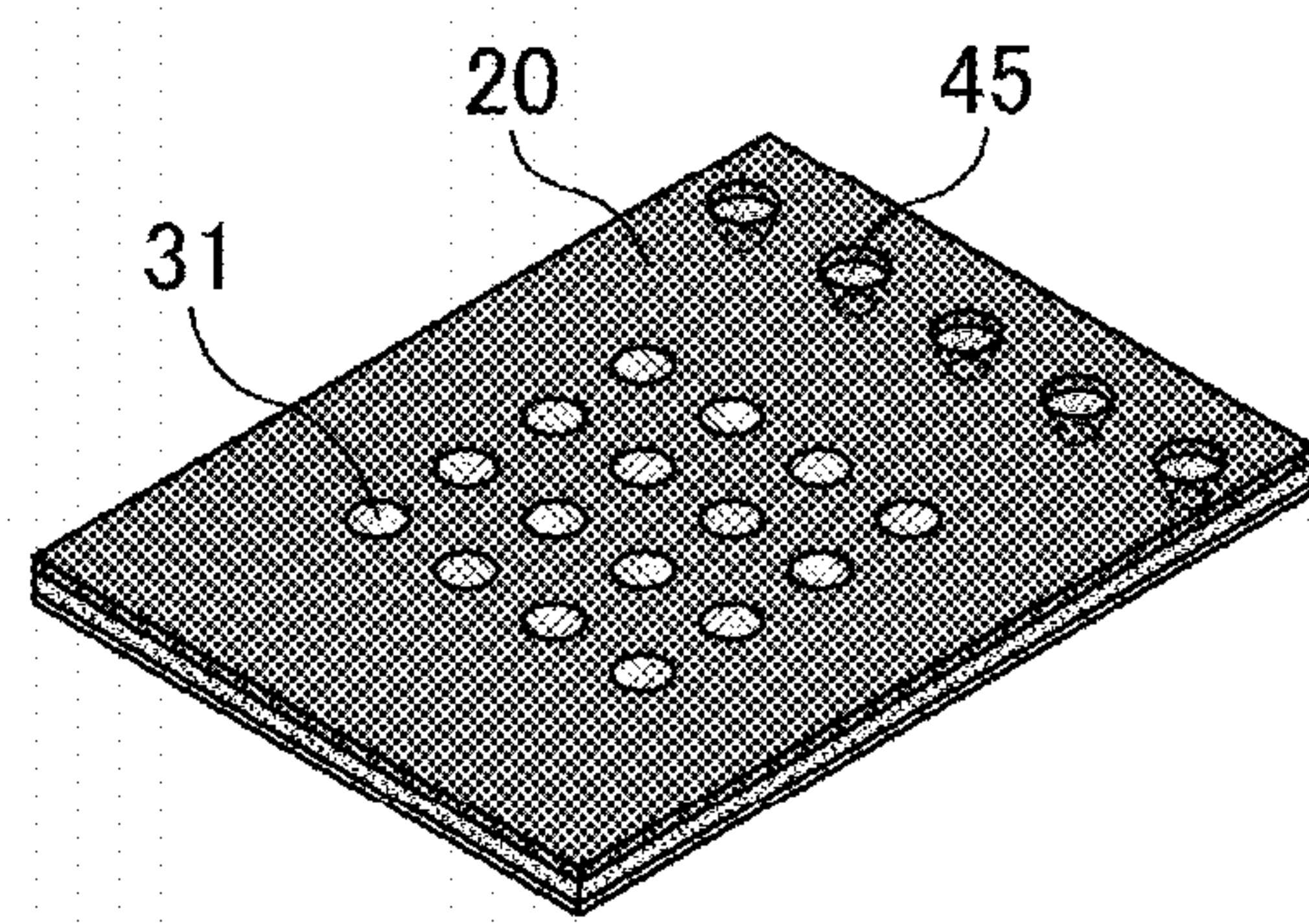


FIG. 2-2 (k)

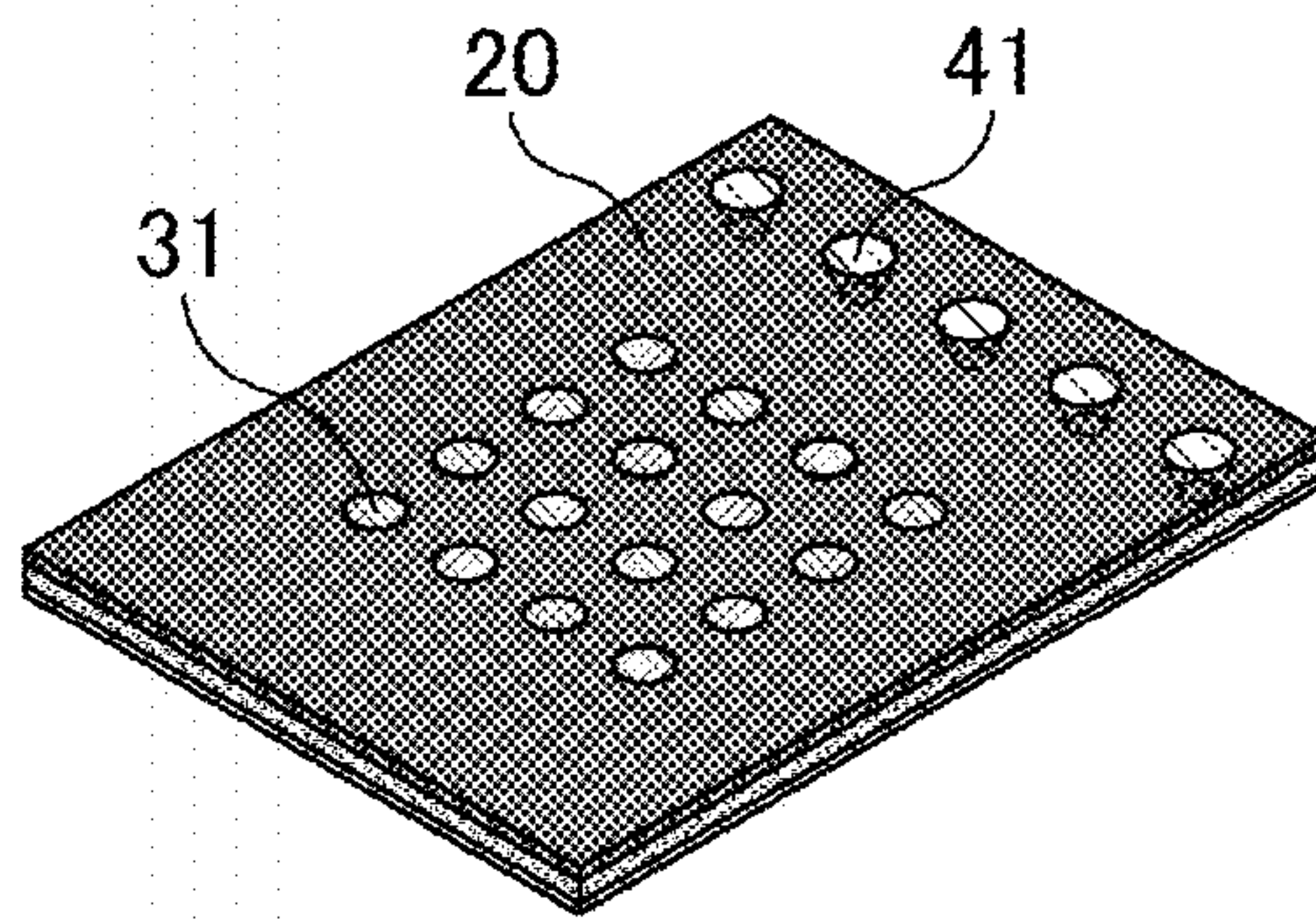


FIG. 2-2 (l)

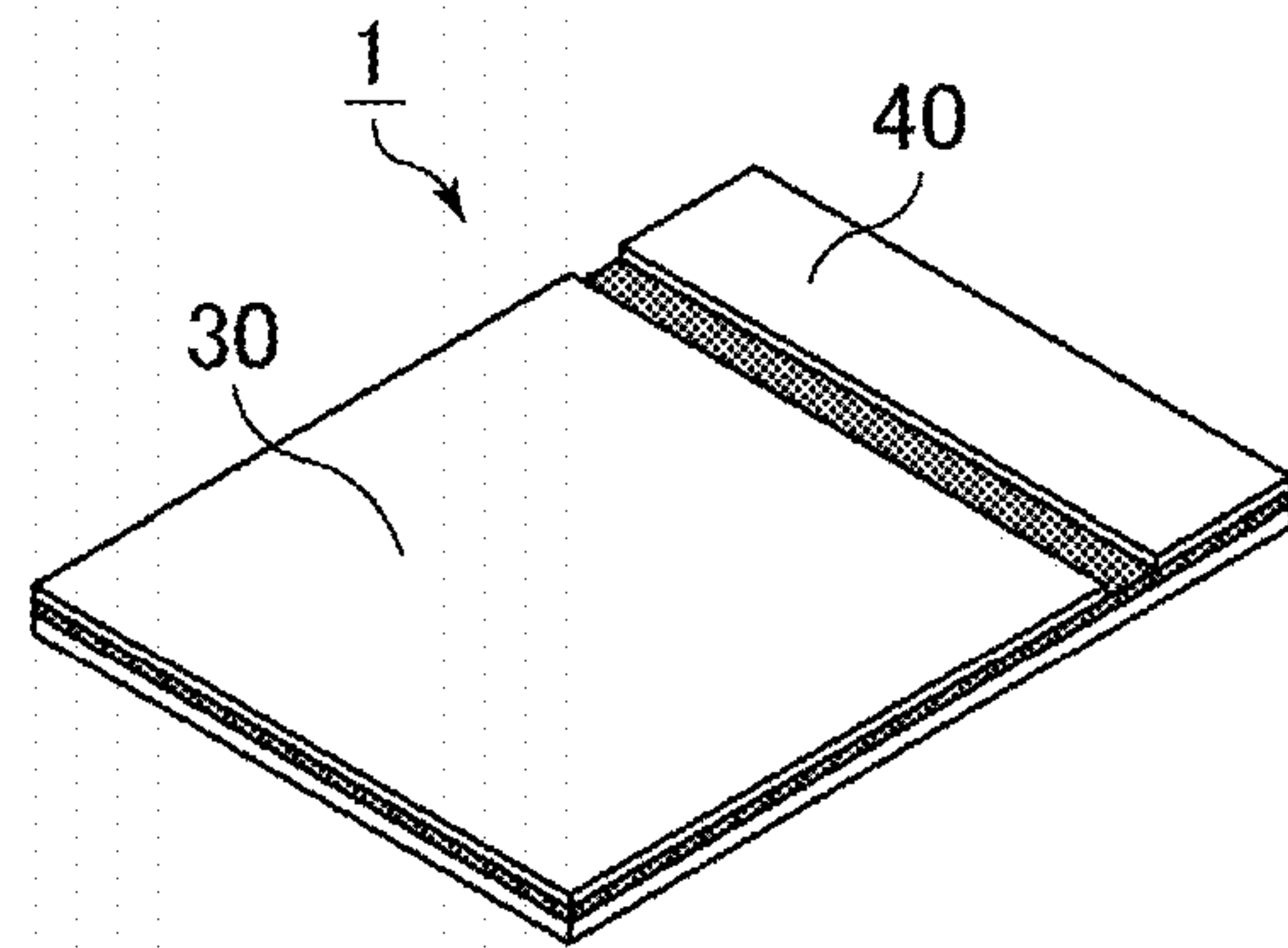


FIG. 3 (a)

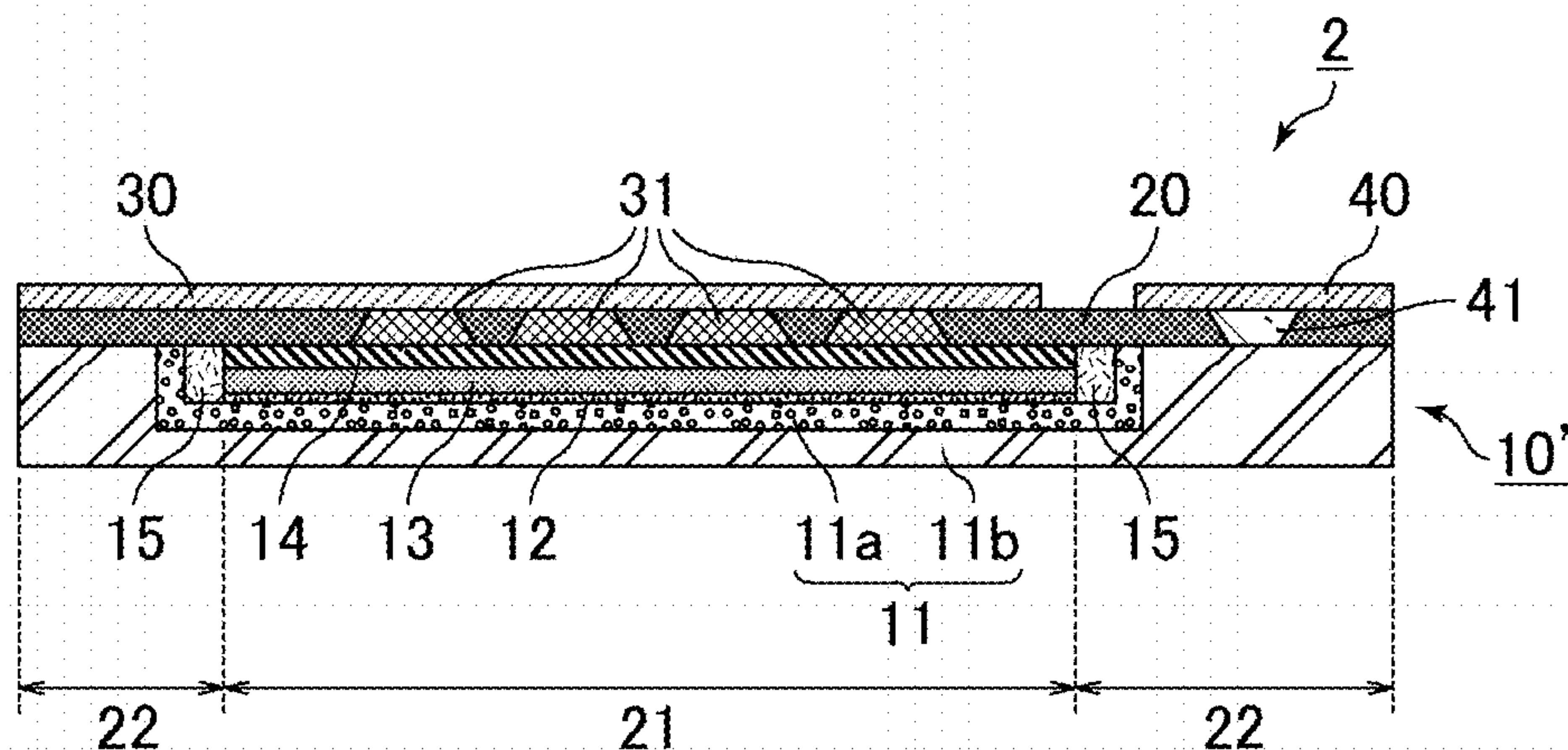


FIG. 3 (b)

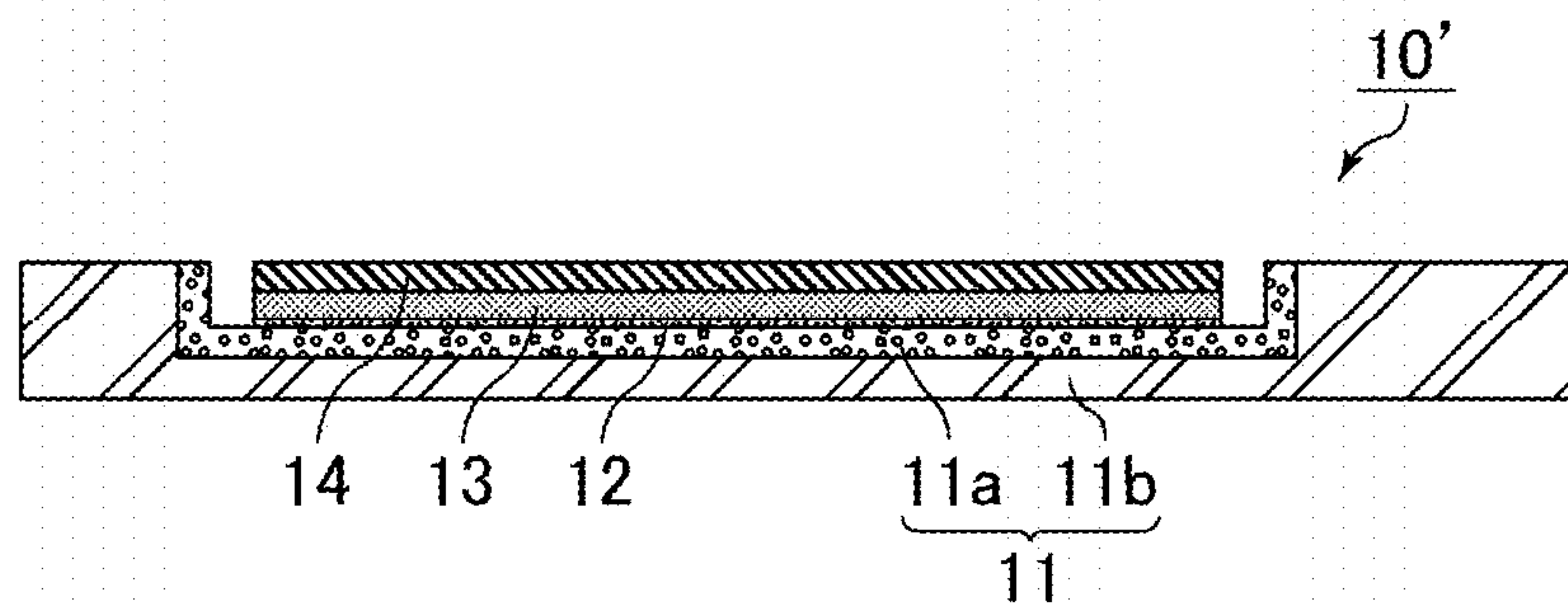


FIG. 3 (c)

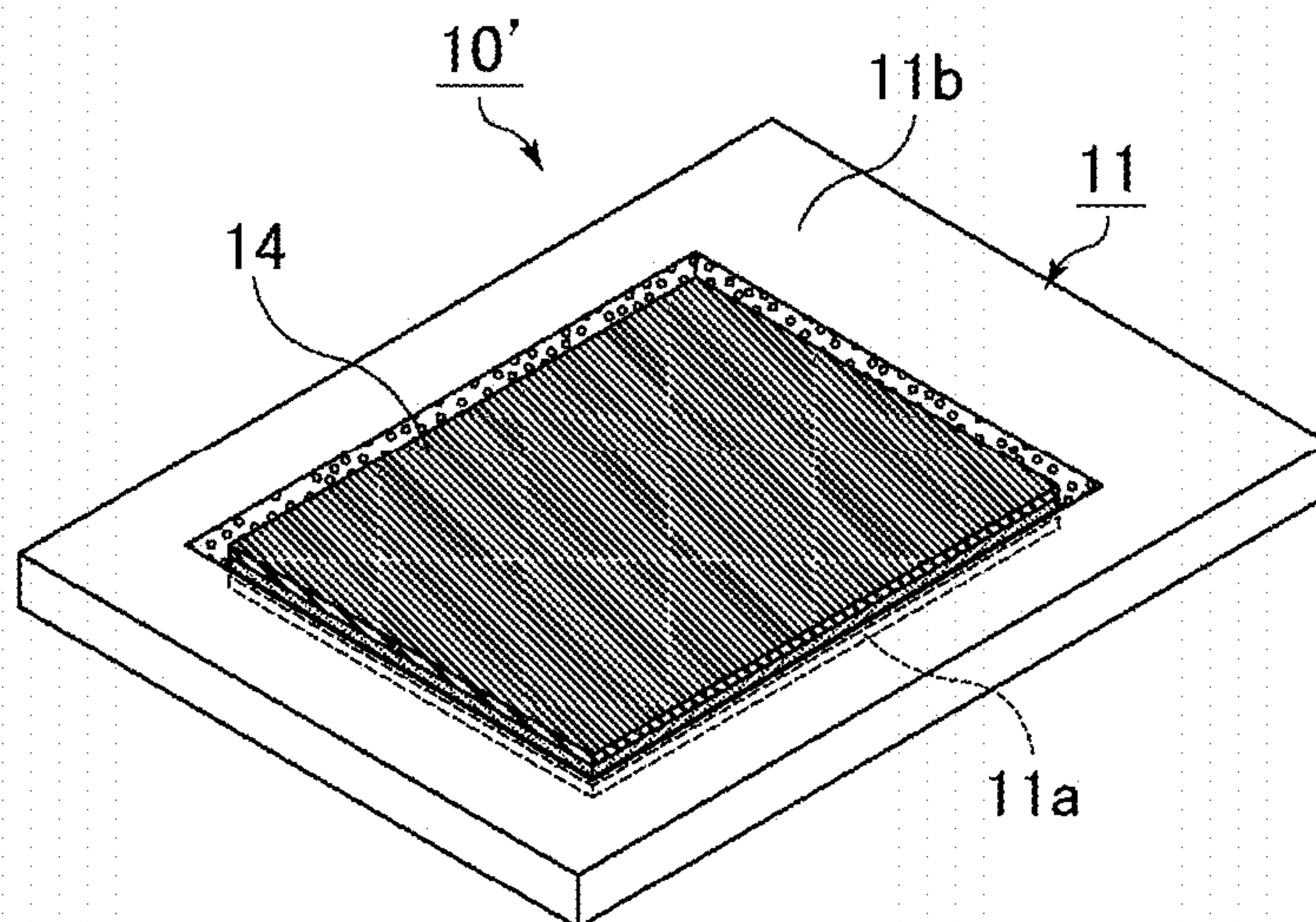


FIG. 4-1(a)

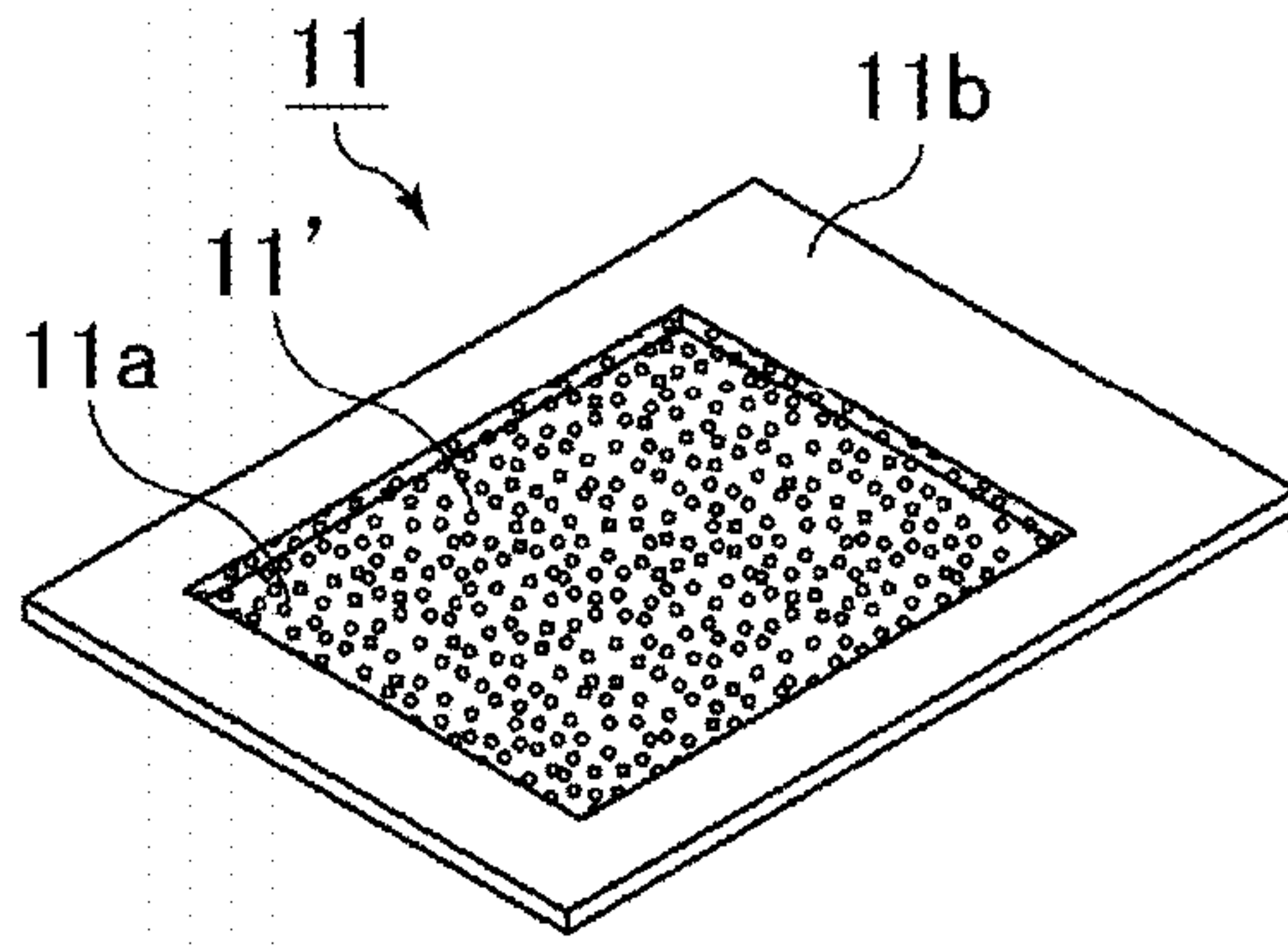


FIG. 4-1(b)

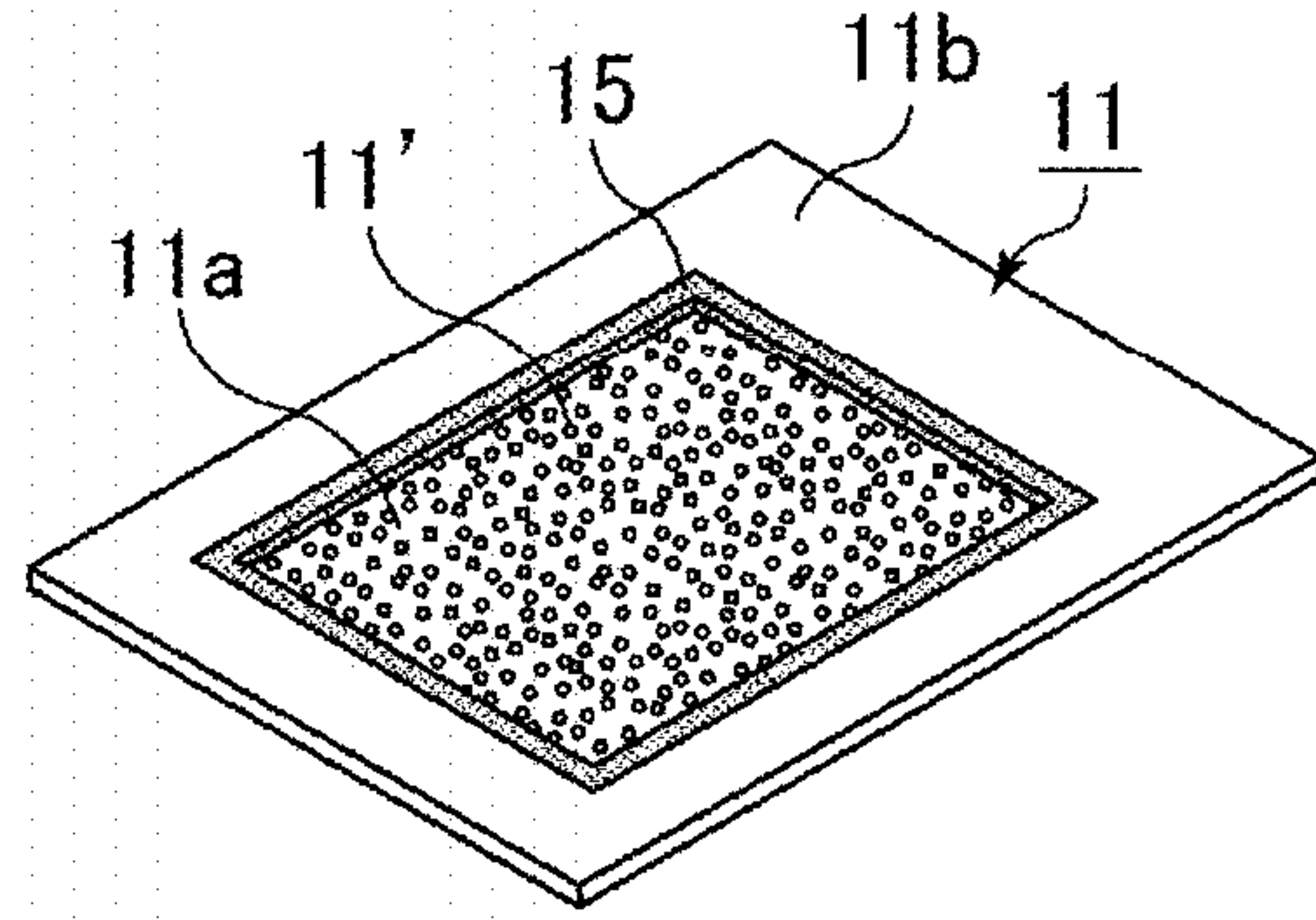


FIG. 4-1(c)

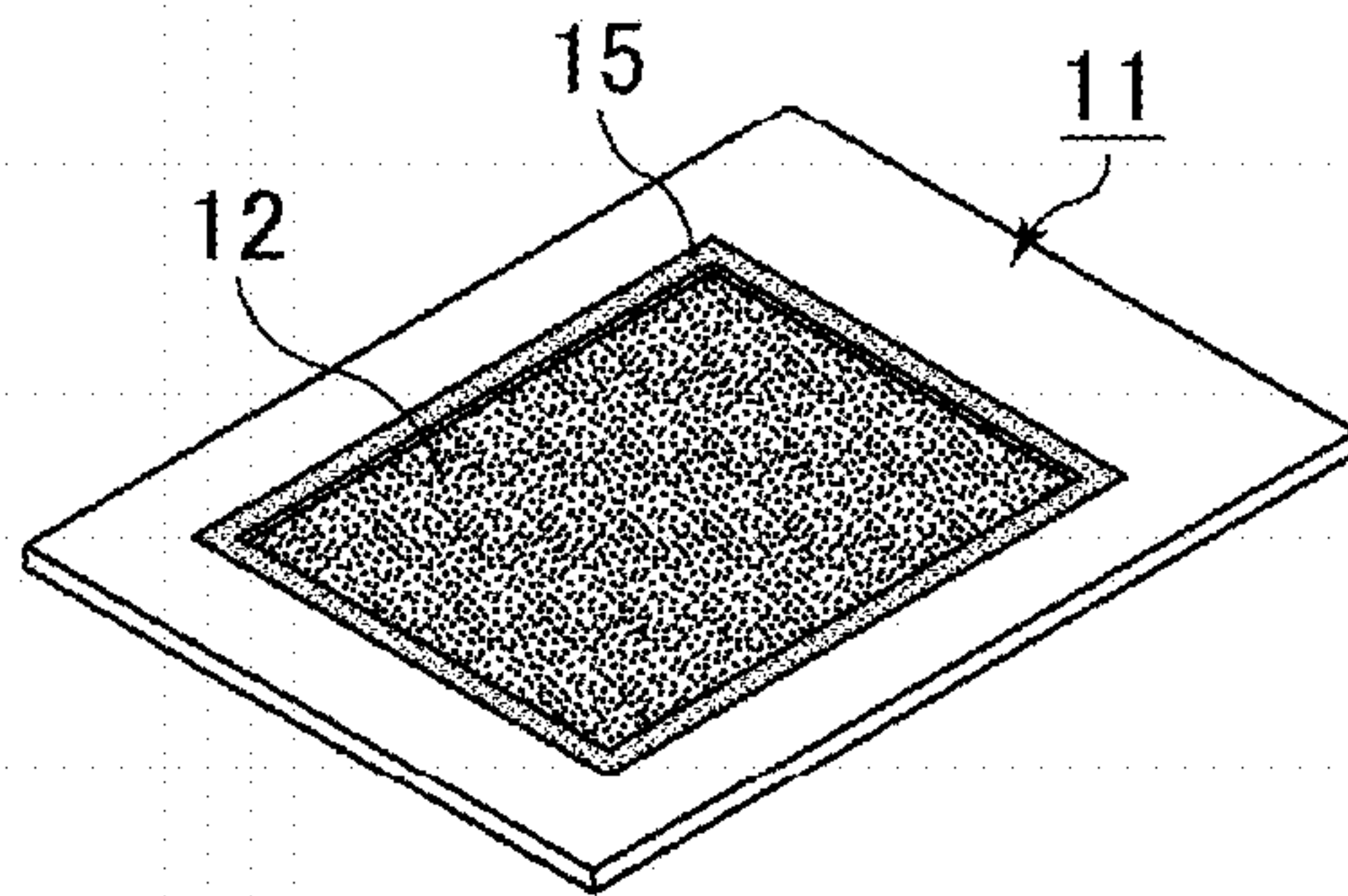


FIG. 4-1(d)

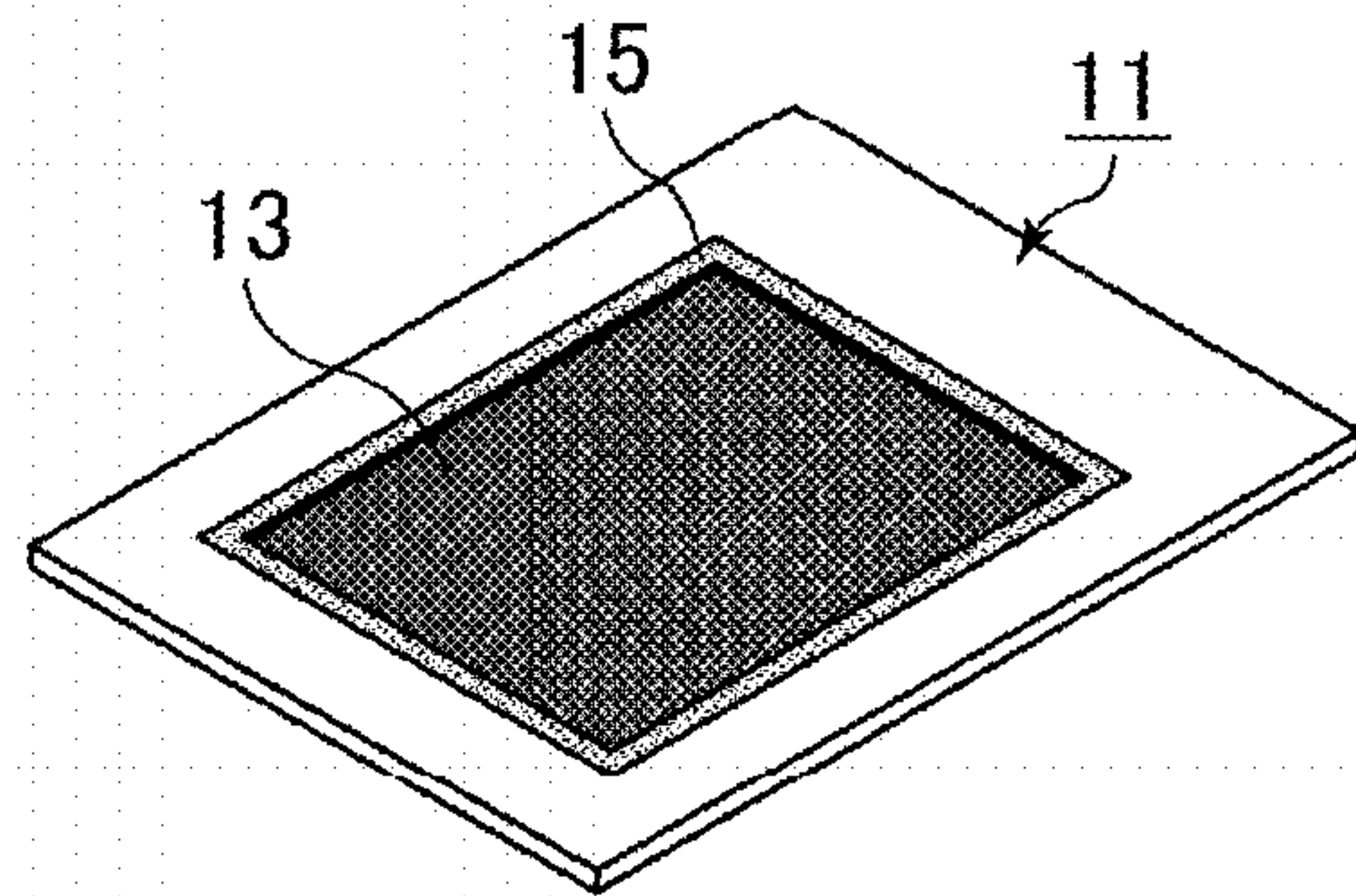


FIG. 4-1(e)

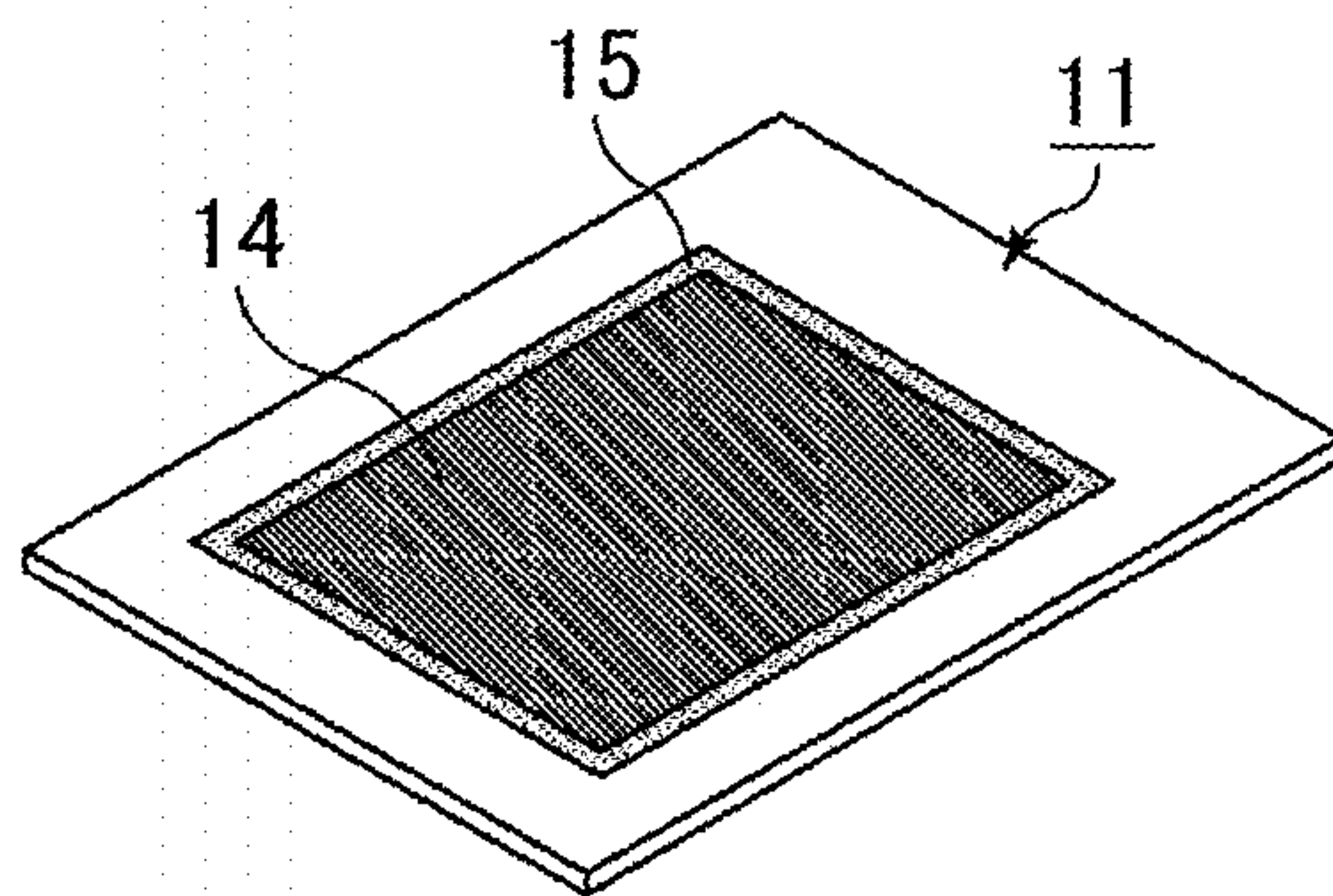


FIG. 4-2 (f)

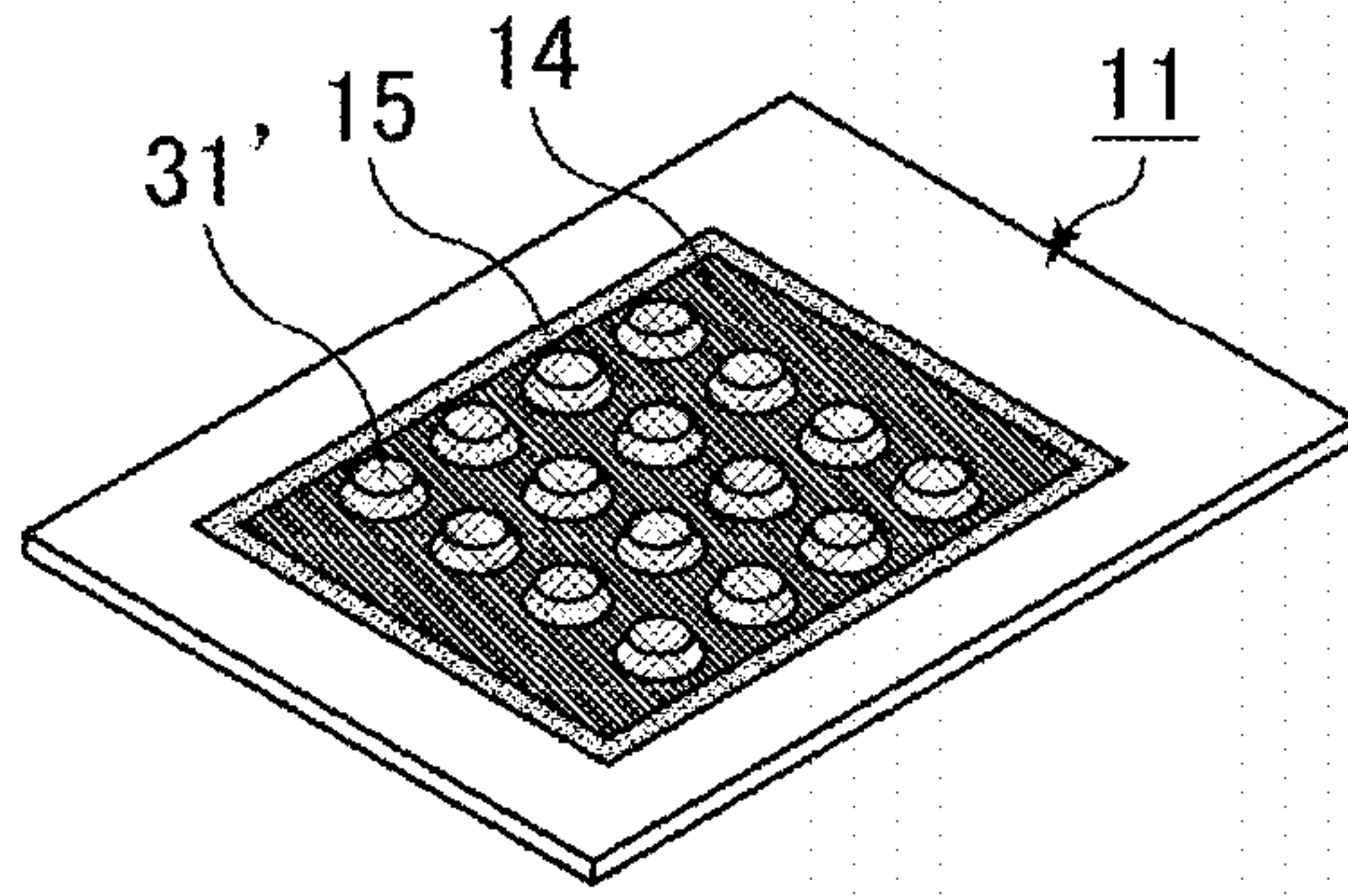


FIG. 4-2 (g)

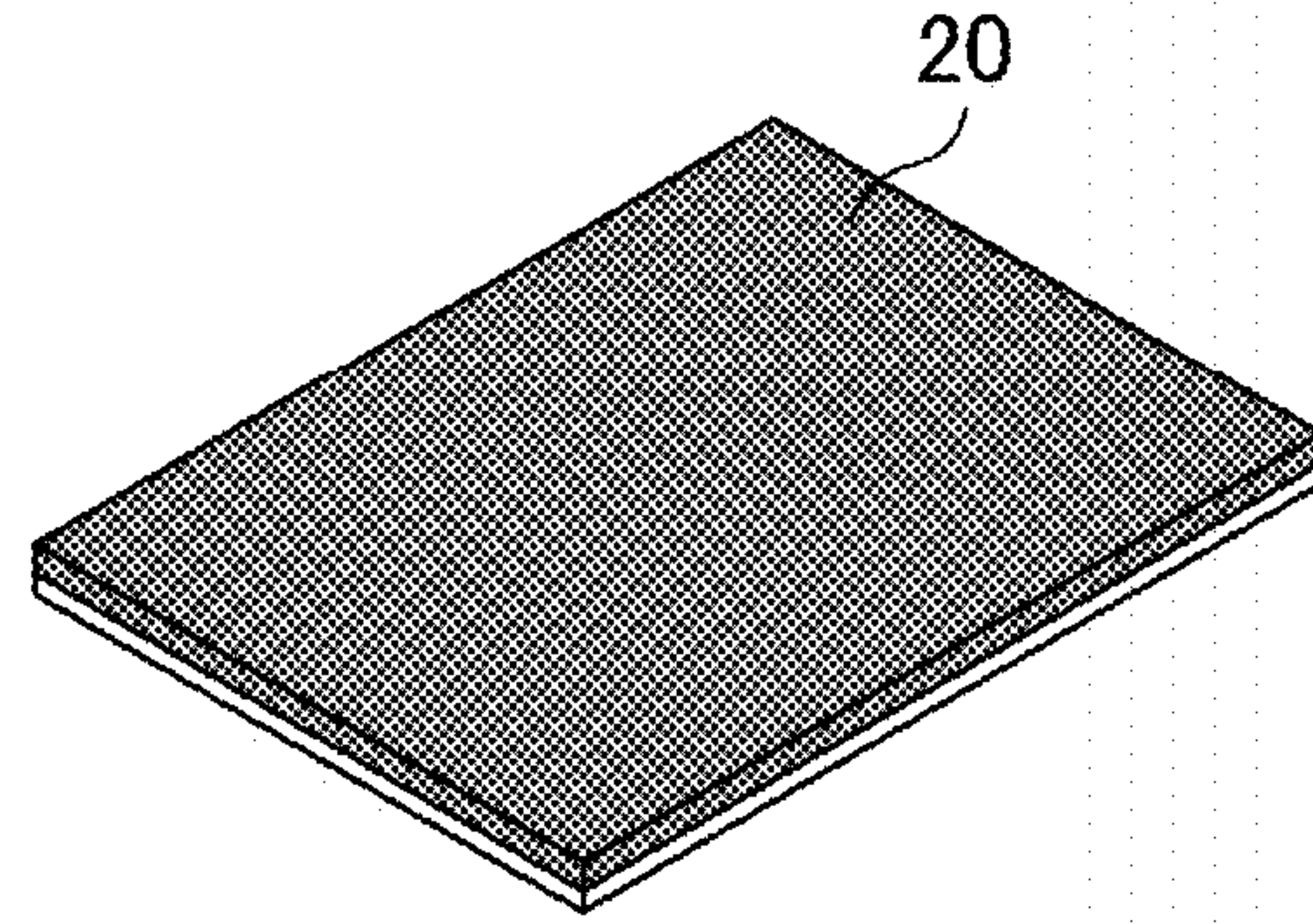


FIG. 4-2 (h)

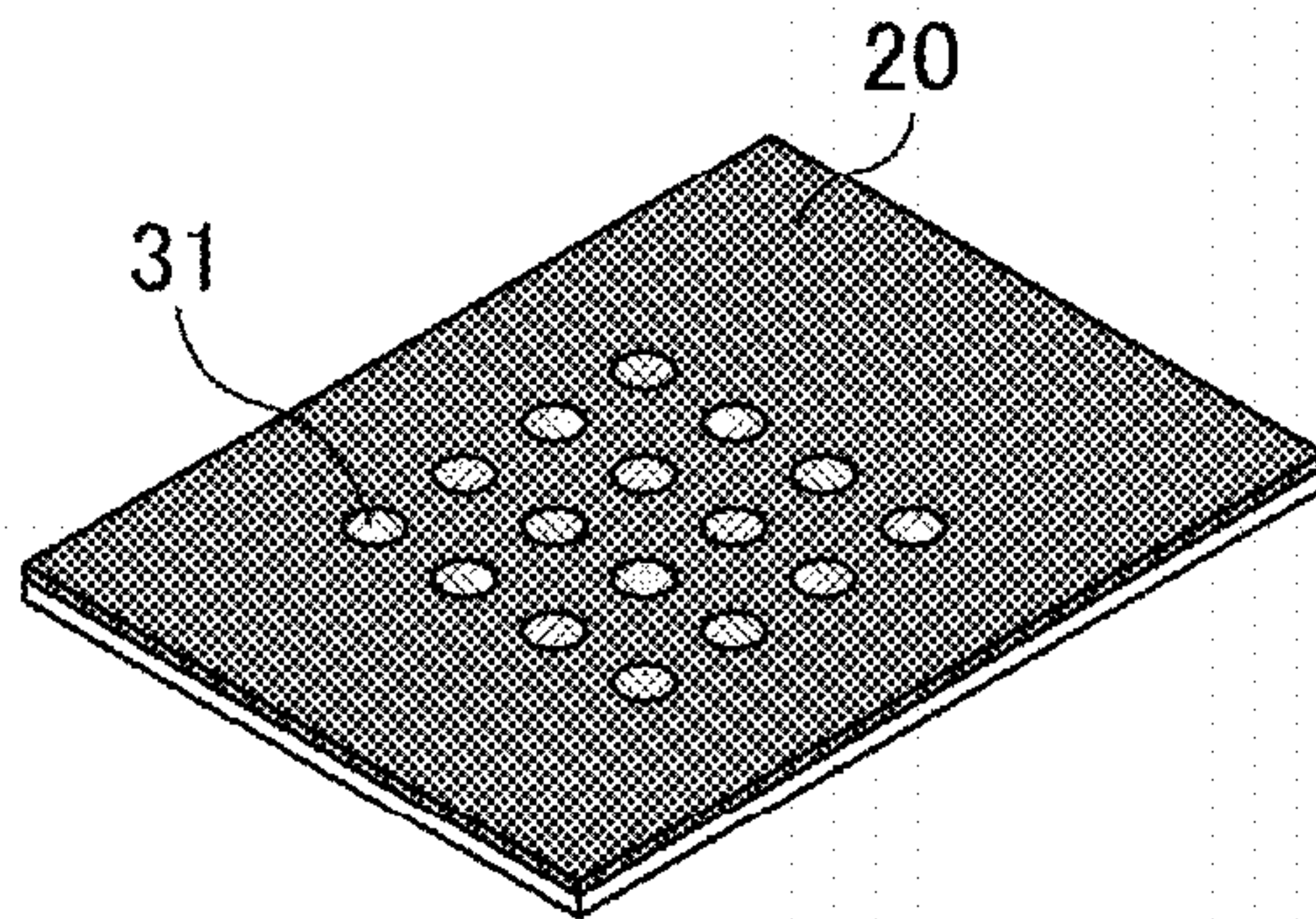


FIG. 4-2 (i)

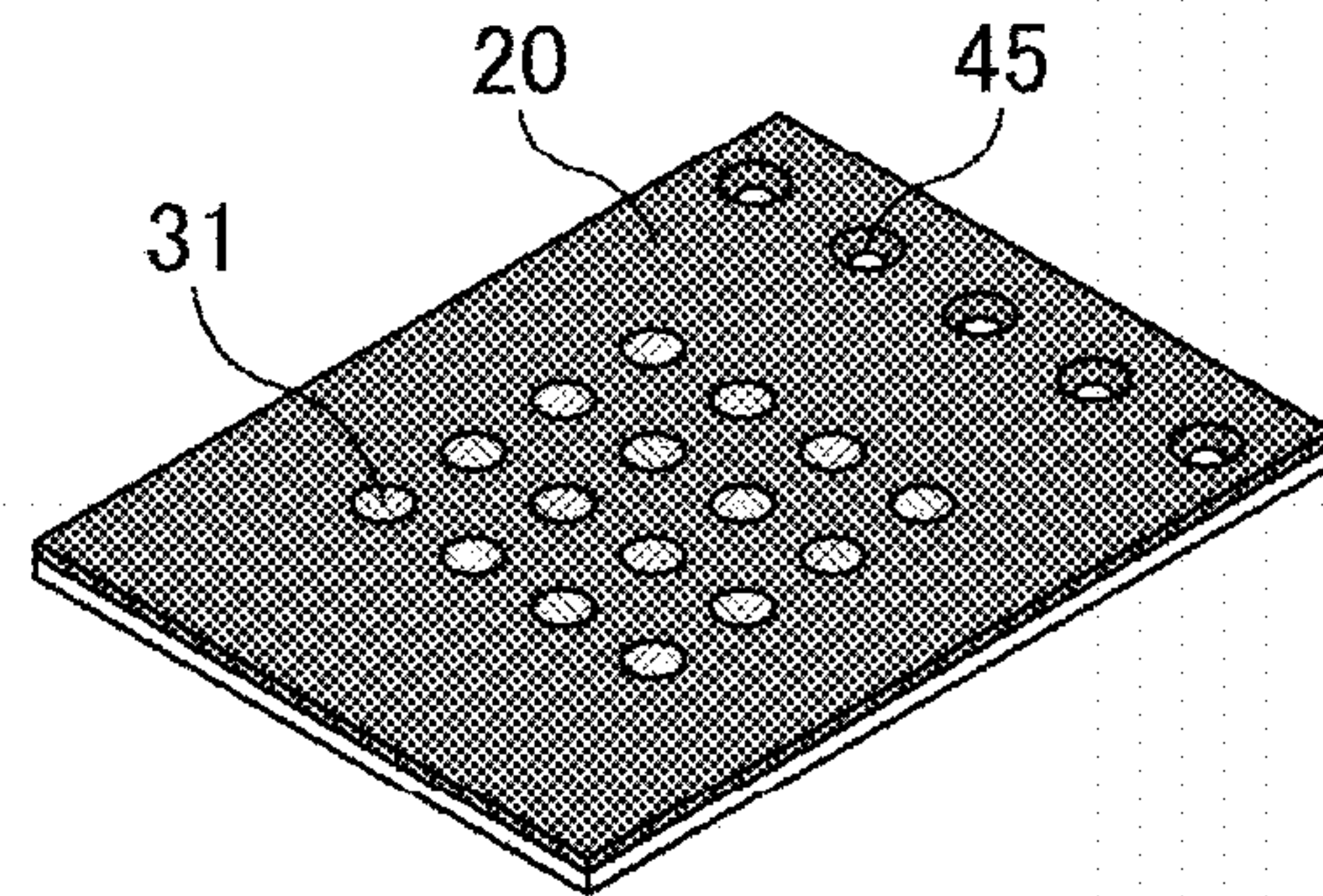


FIG. 4-2 (j)

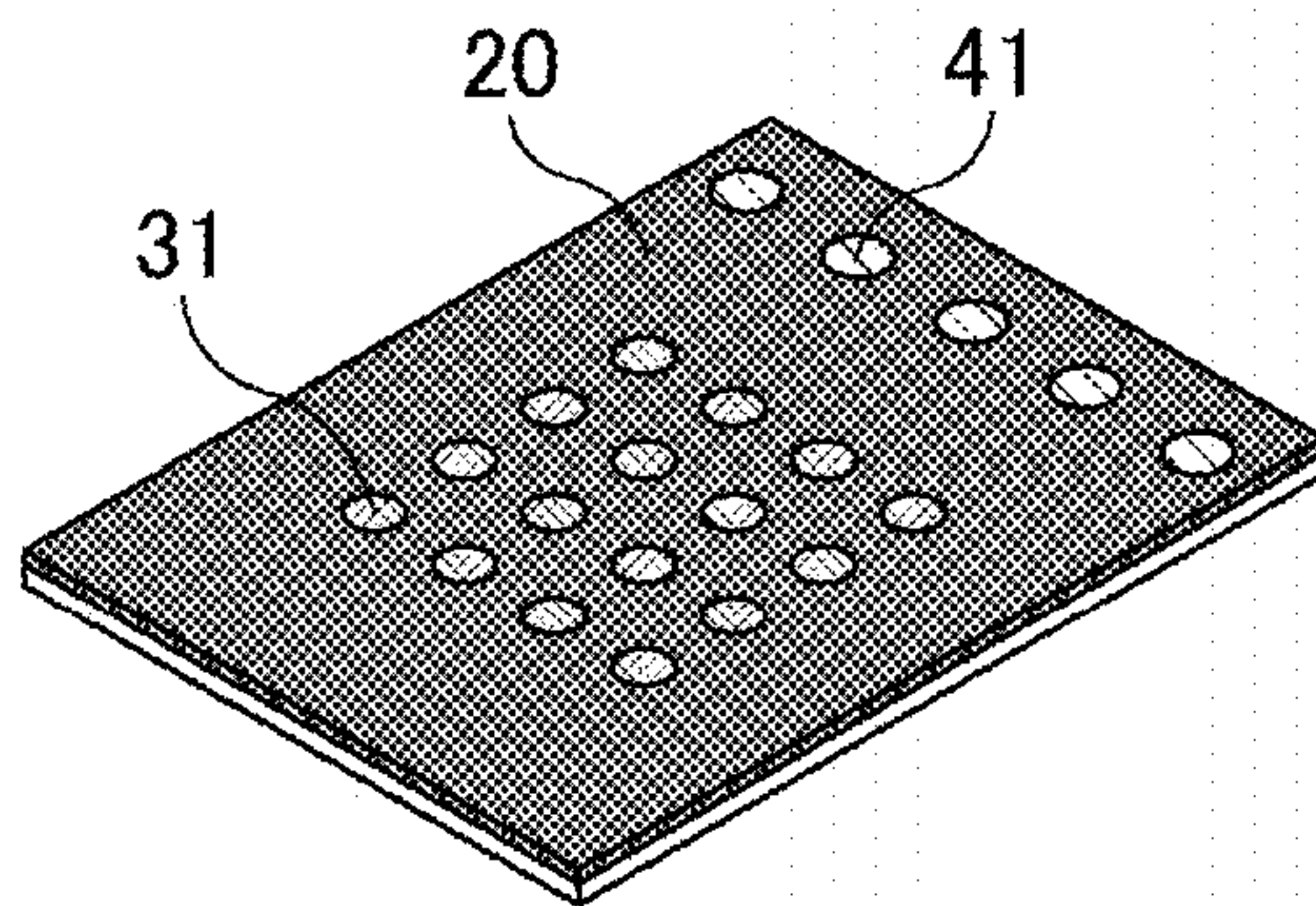
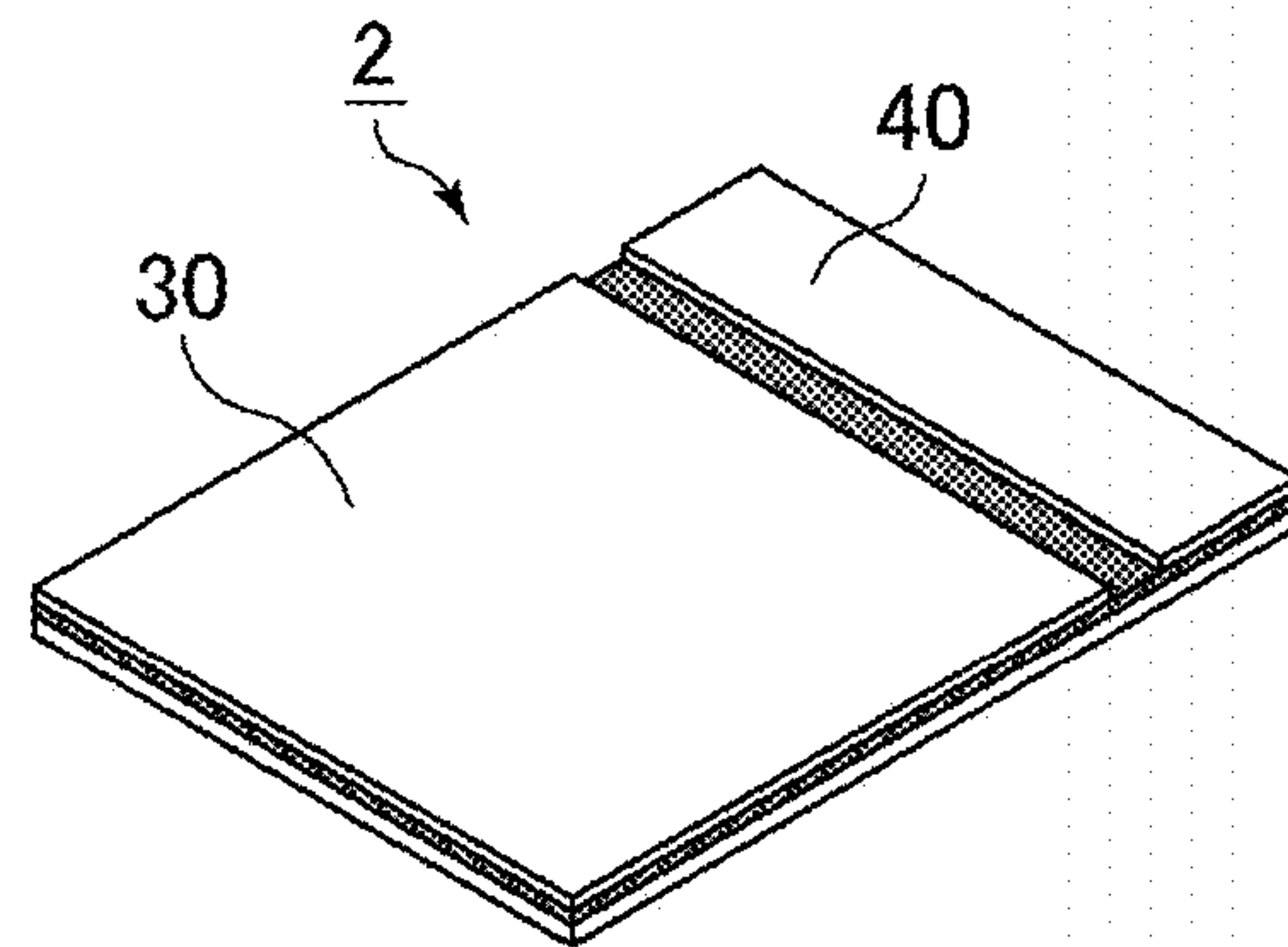


FIG. 4-2 (k)



SOLID ELECTROLYTIC CAPACITOR**CROSS REFERENCE TO RELATED APPLICATIONS**

The present application is a continuation of International application No. PCT/JP2017/030336, filed Aug. 24, 2017, which claims priority to Japanese Patent Application No. 2016-197929, filed Oct. 6, 2016, the entire contents of each of which are incorporated herein by reference.

TECHNICAL FIELD

The present invention relates to a solid electrolytic capacitor.

BACKGROUND OF THE INVENTION

Solid electrolytic capacitors typically include a capacitor element that includes a valve-acting metal substrate including a core part composed of a valve metal, such as aluminum, and a porous part formed in the surface of the core part, a dielectric layer formed in the surface of the porous part, a solid electrolyte layer disposed on the dielectric layer, and a conductive layer disposed on the solid electrolyte layer.

Japanese Unexamined Patent Application Publication No. 2008-135427 discloses a solid electrolyte capacitor wherein a plurality of capacitor elements are stacked on top of one another, the capacitor elements are then electrically connected to a lead frame, and resin sealing is subsequently performed by transfer molding or the like. In another case, the capacitor elements are electrically connected to a mount board, such as a printed circuit board, instead of a lead frame and resin sealing is subsequently performed.

The part of a solid electrolytic capacitor which is responsible for the formation of electrostatic capacity (hereinafter, such a part is referred to as "capacitance formation part") is the porous part, such as an etched layer, in which the dielectric layer is formed. In the production methods used in the related art, it is difficult to increase the ratio of the volume of the capacitance formation part to the overall volume of the capacitor. Thus, it has been difficult to produce a thin solid electrolytic capacitor.

The present invention was made in order to, inter alia, address the above issues. An object of the present invention is to provide a solid electrolytic capacitor that may have a small thickness.

BRIEF SUMMARY OF THE INVENTION

The solid electrolytic capacitor according to the present invention includes a capacitor element including a valve-acting metal substrate including a core part and a porous part disposed on at least one principal surface of the core part, a dielectric layer formed in a surface of the porous part, a solid electrolyte layer disposed on the dielectric layer, and a conductive layer disposed on the solid electrolyte layer; a sealing resin with which a principal surface of the capacitor element is sealed; a cathodic outer electrode electrically connected to the conductive layer; and an anodic outer electrode electrically connected to the core part.

In a first embodiment of the present invention, an insulating layer is interposed between the core part and the sealing resin; the insulating layer, the sealing resin, and the anodic outer electrode are disposed on and above the core part in this order; a first anodic via electrode is formed in the sealing resin disposed on the insulating layer so as to

penetrate the sealing resin, and a second anodic via electrode is formed in the insulating layer disposed on the core part so as to penetrate the insulating layer; the core part is electrically drawn to a surface of the sealing resin through the first and second anodic via electrodes; and the first anodic via electrode exposed at the surface of the sealing resin is connected to the anodic outer electrode.

In the first embodiment of the present invention, on a principal surface of the valve-acting metal substrate, a surface of the core part is preferably at a lower level than the surface of the porous part.

In the first embodiment of the present invention, the first and second anodic via electrodes may be plated electrodes; and the first and second anodic via electrodes may be paste electrodes including a material formed by curing a conductive paste.

In the first embodiment of the present invention, each of the first and second anodic via electrodes preferably has a reversely tapered cross-sectional shape, the width of the reversely tapered cross-sectional shape increasing in the direction from the core part toward the anodic outer electrode.

In the first embodiment of the present invention, the first and second anodic via electrodes may be columnar metal pins.

In the first embodiment of the present invention, the insulating layer may be composed of the same material as the sealing resin.

In a second embodiment of the present invention, the sealing resin and the anodic outer electrode are disposed on and above the core part in this order; a first anodic via electrode is formed in the sealing resin disposed on the core part so as to penetrate the sealing resin; the first anodic via electrode is arranged to come into direct contact with the core part; the core part is electrically drawn to a surface of the sealing resin through the first anodic via electrode; and the first anodic via electrode exposed at the surface of the sealing resin is connected to the anodic outer electrode.

In the second embodiment of the present invention, on a principal surface of the valve-acting metal substrate, a surface of the core part is preferably at a higher level than the surface of the porous part or at the same level as the surface of the porous part.

In the second embodiment of the present invention, the first anodic via electrode may be a plated electrode; and the first anodic via electrode may be a paste electrode including a material formed by curing a conductive paste.

In the second embodiment of the present invention, the first anodic via electrode preferably has a reversely tapered cross-sectional shape, the width of the reversely tapered cross-sectional shape increasing in the direction from the core part toward the anodic outer electrode.

In the second embodiment of the present invention, the first anodic via electrode may be a columnar metal pin.

In the solid electrolytic capacitor according to the present invention, when viewed in the direction of the normal to the principal surface of the capacitor element, the anodic outer electrode preferably has a larger size than the first anodic via electrode so as to cover the first anodic via electrode.

In the solid electrolytic capacitor according to the present invention, it is preferable that the sealing resin and the cathodic outer electrode be disposed on and above the conductive layer in this order; a cathodic via electrode be formed in the sealing resin disposed on the conductive layer so as to penetrate the sealing resin; the conductive layer be electrically drawn to the surface of the sealing resin through

the cathodic via electrode; and the cathodic via electrode exposed at the surface of the sealing resin be connected to the cathodic outer electrode.

The cathodic via electrode may be a paste electrode including a material formed by curing a conductive paste. The cathodic via electrode may be a columnar metal pin.

It is preferable that, when viewed in the direction of the normal to the principal surface of the capacitor element, the cathodic outer electrode have a larger size than the cathodic via electrode so as to cover the cathodic via electrode.

In the solid electrolytic capacitor according to the present invention, the anodic outer electrode and the cathodic outer electrode may be metal electrodes including a metal film; the anodic outer electrode and the cathodic outer electrode may be paste electrodes including a material formed by curing a conductive paste; the anodic outer electrode may be a ball-like terminal; and the cathodic outer electrode may be a ball-like terminal.

In the solid electrolytic capacitor according to the present invention, a surface of the solid electrolytic capacitor, the surface being other than a surface that includes the anodic outer electrode and the cathodic outer electrode, may be covered with another insulating layer.

In the solid electrolytic capacitor according to the present invention, a stress relaxation layer may be interposed between the capacitor element and the sealing resin; and a damp-proof membrane may be interposed between the capacitor element and the sealing resin.

Advantageous Effects of the Invention

According to the present invention, a solid electrolytic capacitor that may have a small thickness can be provided.

BRIEF DESCRIPTION OF DRAWINGS

FIG. 1(a) is a schematic cross-sectional view of an example of a solid electrolytic capacitor according to a first embodiment of the present invention.

FIG. 1(b) is a schematic cross-sectional view of an example of a capacitor element included in the solid electrolytic capacitor illustrated in FIG. 1(a).

FIG. 1(c) is a schematic perspective view of an example of a capacitor element included in the solid electrolytic capacitor illustrated in FIG. 1(a).

FIGS. 2-1(a) through 2-2(l) are schematic perspective views illustrating an example of the method for producing the solid electrolytic capacitor 1 illustrated in FIG. 1(a).

FIG. 3(a) is a schematic cross-sectional view of an example of a solid electrolytic capacitor according to a second embodiment of the present invention.

FIG. 3(b) is a schematic cross-sectional view of an example of a capacitor element included in the solid electrolytic capacitor illustrated in FIG. 3(a).

FIG. 3(c) is a schematic perspective view of an example of a capacitor element included in the solid electrolytic capacitor illustrated in FIG. 3(a).

FIGS. 4-1(a) through 4-2(k) are schematic perspective views illustrating an example of the method for producing the solid electrolytic capacitor 2 illustrated in FIG. 3(a).

DESCRIPTION OF THE PREFERRED EMBODIMENTS

While preferred embodiments of the invention are described below, the present invention is not limited to the structures described. Variations and modifications may be

made without departing from the spirit and scope of the present invention. The present invention also includes a combination of two or more of the desirable structures of the present invention which are described below.

It should be understood that the following embodiments are merely illustrative and partial replacements or combinations of structures described in different embodiments are also possible. In the second embodiment and thereafter, the description of items common to the first embodiment is omitted, and only the differences are described. Especially, similar actions and effects of a similar structure is not mentioned in each of the embodiments.

In the solid electrolytic capacitor, the anode and cathodic outer electrodes may be disposed on the same side. This makes it possible to produce a thin solid electrolytic capacitor. Specifically, arranging the outer electrodes on the surface of the sealing resin eliminates the need to use a thick electrode, such as a mount board or a lead frame. This enables the overall thickness of the product to be reduced while maintaining the thicknesses of the functional layers inside the capacitor element.

First Embodiment

In the first embodiment of the present invention, an insulating layer is interposed between the core part and the sealing resin; the insulating layer, the sealing resin, and the anodic outer electrode are disposed on and above the core part in this order; a first anodic via electrode is formed in the sealing resin disposed on the insulating layer, and a second anodic via electrode is formed in the insulating layer disposed on the core part; and the core part is electrically drawn to the surface of the sealing resin through the first and second anodic via electrodes. One of the structural advantages of the first embodiment of the present invention is that the insulating layer, which comes into direct contact with the porous part, and the sealing resin may be composed of different materials. Since the surface of the cathode part which faces the principal surface of the capacitor element is covered with the sealing resin and the cathodic outer electrode and therefore has a substantially hermetically sealed structure, the possible routes through which moisture may enter from the outside are primarily the insulating layer and the interfaces between the above layers. Forming the insulating layer using a material having high adhesion and high vapor resistance enables the production of a solid electrolytic capacitor having excellent reliability.

In addition, the sealing resin and the cathodic outer electrode are disposed on the conductive layer in this order, a cathodic via electrode is formed in the sealing resin disposed on the conductive layer, and the conductive layer is electrically drawn to the surface of the sealing resin through the cathodic via electrode. Since the functions are concentrated on only one side of the valve-acting metal substrate and the sizes of the functional layers other than the capacitance formation part (the part responsible for the formation of electrostatic capacity) are minimized, the ratio of the volume of the capacitance formation part to the overall volume of the capacitor may be increased. This enables an increase in the volumetric efficiency of the capacitance formation part and the production of a thin solid electrolytic capacitor.

As illustrated in FIGS. 1(a) and 1(b), the solid electrolytic capacitor 1 of the first preferred embodiment includes a capacitor element 10, a sealing resin 20, a cathodic outer electrode 30, and an anodic outer electrode 40. The capacitor element 10 includes a valve-acting metal substrate 11 which

includes a core part **11b** and a porous part **11a** disposed on a principal surface of the core part **11b**, a dielectric layer **12** formed on the surface of the porous part **11a**, a solid electrolyte layer **13** disposed on the dielectric layer **12**, and a conductive layer **14** disposed on the solid electrolyte layer **13**. An insulating layer **15** is disposed on the outer periphery of the core part **11b** and insulates the sealing resin **20** from the core part **11b** and the lateral edges of the porous part **11a** as illustrated in FIG. **1(a)**.

In the solid electrolytic capacitor **1** illustrated in FIG. **1(a)**, the top surface of the valve acting metal substrate **11** includes the top surface of the porous part **11a** and the top surface of the core part **11b** located laterally outward of the porous part (i.e., left and right of the porous part **11a** as viewed in FIGS. **1(a)** and **1(b)**). In this embodiment, the top surface of the core part **11b** is located below the top surface of the porous part **11a**. Alternatively, the top surface of the core part **11a** can be above or at the same level as the top surface of the porous part **11a**. The foregoing references to “top surface” is with reference to the orientation of the core part **11b** and the porous part **11a** as viewed in FIGS. **1(a)** and **1(b)**.

It is preferable that the porous part **11a** be disposed at the center of the valve-acting metal substrate **11** and the core part **11b** be disposed both at the center and on the peripheral portion of the valve-acting metal substrate **11** as illustrated in FIGS. **1(b)** and **1(c)**.

In this embodiment, the upper principal surface of the capacitor element **10** is sealed with the sealing resin **20** such that the sealing resin **20** is disposed on the conductive layer **14** and the insulating layer **15** and covers the entire upper principal surface of the capacitor element **10**.

A principal surface of the capacitor element **10** is sealed with the sealing resin **20**. In the solid electrolytic capacitor **1** illustrated in FIG. **1(a)**, the sealing resin **20** is disposed on the conductive layer **14** and the insulating layer **15** so as to cover the principal surface of the capacitor element **10**.

The cathodic outer electrode **30** is electrically connected to the conductive layer **14**. In the solid electrolytic capacitor **1** illustrated in FIG. **1(a)**, the sealing resin **20** and the cathodic outer electrode **30** are disposed on and above the conductive layer **14** in this order, and cathodic via electrodes **31** are formed in the sealing resin **20** disposed on the conductive layer **14** so as to penetrate the sealing resin **20**. The conductive layer **14** (a cathode part **21**) is electrically drawn to the surface of the sealing resin **20** by the cathodic via electrodes **31**. The portion of the cathodic via electrodes **31** exposed at the upper surface of the sealing resin **20** are connected to the cathodic outer electrode **30**.

The form of the cathodic via electrodes **31** is not limited. The cathodic via electrodes **31** may be, for example, paste electrodes. The term “paste electrode” used herein refers to an electrode composed of a material formed by curing a conductive paste. Cathodic via electrodes **31** that are paste electrodes may be readily formed by forming bump electrodes, covering the bump electrodes with the sealing resin, and trimming the sealing resin as described below.

In the example illustrated in FIG. **1(a)**, the cathodic via electrodes **31** have a tapered cross-sectional shape the width of which increases in the direction from the cathodic outer electrode **30** toward the conductive layer **14**. In the case where the cathodic via electrodes **31** are paste electrodes, the cathodic via electrodes **31** may have the tapered cross-sectional shape or a rectangular cross-sectional shape the width of which substantially does not change in the direction from the cathodic outer electrode **30** toward the conductive layer **14**.

The cathodic via electrodes **31** may be columnar metal pins. In the case where the cathodic via electrodes **31** are the metal pins, the cathodic via electrodes **31** preferably have a rectangular cross-sectional shape the width of which substantially does not change in the direction from the cathodic outer electrode **30** toward the conductive layer **14**. Examples of the shape of the metal pins include a cylindrical shape.

Although four cathodic via electrodes **31** are illustrated in FIG. **1(a)**, more or less cathodic via electrodes **31** may be used. The number of the cathodic via electrodes **31** is at least one.

The height of the cathodic via electrodes **31** is preferably equal to the thickness of the sealing resin **20**. The height of the cathodic via electrodes **31** is not limited and preferably 5 μm or more and 200 μm or less.

The form of the cathodic outer electrode **30** is not limited. The cathodic outer electrode **30** may be, for example, a metal electrode or a paste electrode. The term “metal electrode” used herein refers to an electrode composed of a metal film. Examples of the metal film include a plating film, a sputtered film, and a vapor-deposited film.

In the case where the cathodic outer electrodes **30** are a metal electrode, the anodic outer electrode **40** is preferably also a metal electrode and may be a paste electrode. Similarly, in the case where the cathodic outer electrodes **30** are a paste electrode, the anodic outer electrode **40** is preferably also a paste electrode and may be a metal electrode. In the case where a metal electrode is used, the outer electrode is preferably grown directly on the surface of the metal constituting the via electrodes. This may reduce the electric resistance. In the case where paste electrodes are used, the adhesion of the outer electrode to the via electrodes is increased. This may enhance the reliability.

The shape of the cathodic outer electrodes **30** is also preferably not limited. When viewed in the direction of the normal to a principal surface of the capacitor element **10**, the cathodic outer electrode **30** preferably has a larger size than the cathodic via electrodes **31** so as to cover the cathodic via electrodes **31**.

The cathodic outer electrode **30** may be a ball-like terminal disposed on the cathodic via electrodes **31**. Examples of the ball-like terminal include a BGA (ball grid array) terminal.

The anodic outer electrode **40** is electrically connected to the core part **11b**. In the solid electrolytic capacitor **1** illustrated in FIG. **1(a)**, the insulating layer **15**, the sealing resin **20**, and the anodic outer electrode **40** are disposed on and above the core part **11b** in this order. A first anodic via electrode **41** is formed in the sealing resin **20** disposed on the insulating layer **15** so as to penetrate the sealing resin **20**. A second anodic via electrode **42** is preferably formed in the insulating layer **15** disposed on the core part **11b** so as to penetrate the insulating layer **15**. The core part **11b** (an anode part **22**) is electrically drawn to the surface of the sealing resin **20** through the first and second anodic via electrodes **41** and **42**. The first anodic via electrode **41** exposed at the surface of the sealing resin **20** is connected to the anodic outer electrode **40**. Although FIG. **1(a)** illustrates a boundary line between the first and second anodic via electrodes **41** and **42** in order to distinguish the first and second anodic via electrodes **41** and **42** from each other, the first and second anodic via electrodes may be formed in one continuous piece.

The form of the first anodic via electrode **41** is not limited. The first anodic via electrode **41** may be, for example, a plated electrode or a paste electrode. The form of the second anodic via electrode **42** is also not limited. The second

anodic via electrode **42** may be, for example, a plated electrode or a paste electrode. In the case where the first anodic via electrode **41** is a plated electrode, the second anodic via electrode **42** is preferably also a plated electrode and may be a paste electrode. Similarly, in the case where the first anodic via electrode **41** is a paste electrode, the second anodic via electrode **42** is preferably also a paste electrode and may be a plated electrode.

In the example illustrated in FIG. 1(a), the first and second anodic via electrodes **41** and **42** each have a reversely tapered cross-sectional shape, i.e., one where the width of the via electrode increases in the direction from the core part **11b** toward the anodic outer electrode **40**. In the case where the first and second anodic via electrodes **41** and **42** are plated electrodes, the first and second anodic via electrodes **41** and **42** preferably have the reversely tapered cross-sectional shape. In such a case, it becomes possible to increase the size of the capacitance formation part while maintaining the area of the region that can be sealed with the resin. Furthermore, when the first and second anodic via electrodes **41** and **42** have the reversely tapered cross-sectional shape, a high fill-up efficiency may be achieved during plating.

The first and second anodic via electrodes **41** and **42** may be columnar metal pins. In the case where the first and second anodic via electrodes **41** and **42** are metal pins, the first and second anodic via electrodes **41** and **42** preferably have a rectangular cross-sectional shape the width of which substantially does not change in the direction from the anodic outer electrode **40** toward the core part **11b**. Examples of the shape of the metal pins include a cylindrical shape.

Although a single first anodic via electrode **41** and a single second anodic via electrode **42** are illustrated in FIG. 1(a), more via electrodes **41** and **42** may be used. Although the anode part **22** is present on the left and right sides of the solid electrolytic capacitor **1** illustrated in FIG. 1(a) and the first and second anodic via electrodes **41** and **42** are formed in the right anode part **22**, the first and second anodic via electrodes **41** and **42** may be also formed in the left anode part **22**.

The form of the anodic outer electrode **40** is not limited. The anodic outer electrode **40** may be, for example, a metal electrode or a paste electrode.

The shape of the anodic outer electrode **40** is also not limited. When viewed in the direction of the normal to a principal surface of the capacitor element **10**, the anodic outer electrode **40** preferably has a larger size than the first anodic via electrode **41** so as to cover the first anodic via electrode **41**.

The anodic outer electrode **40** may be a ball-like terminal disposed on the first anodic via electrode **41**. Examples of the ball-like terminal include a BGA (ball grid array) terminal.

In FIG. 1(a), the cathodic outer electrode **30** and the anodic outer electrode **40** are arranged so that they do not come into contact with each other and are insulated from each other on the surface of the sealing resin **20**.

Various modifications are possible. For example, a surface of the solid electrolytic capacitor **1** other than the surface that includes the anodic outer electrode **40** and the cathodic outer electrode **30** may optionally be covered with another insulating layer in order to protect the other surface. By way of another example, example, a stress relaxation layer and a damp-proof membrane may optionally be interposed between the capacitor element and the sealing resin in order to protect the capacitor element.

The valve-acting metal substrate included in the solid electrolytic capacitor according to the present invention is composed of a valve-action metal that has a "valve action". Examples of the valve-action metal include metal elements such as aluminum, tantalum, niobium, titanium, and zirconium and alloys including the above metal elements. Among the above valve-action metals, aluminum and an aluminum alloy are preferable.

The valve-acting metal substrate is preferably plate-like in shape and is more preferably foil-like in shape. The porous part and the core part are disposed on at least one principal surface of the valve-acting metal substrate. Alternatively, the porous part and the core part may be disposed on each of the opposed principal (typically opposed) surfaces of the valve-acting metal substrate. Other variations are possible. The porous part is preferably an etched layer formed in the surface of the core part.

The thickness of the core part is preferably 5 or more and 100 μm or less. The thickness of the porous part (the thickness of one porous part except the core part) is preferably 5 μm or more and 200 μm or less.

In the solid electrolytic capacitor according to the present invention, the dielectric layer is preferably formed in the surface of the porous part of the valve-acting metal substrate. Reflecting the conditions of the surface of the porous part, the dielectric layer disposed in the surface of the porous part is porous and has a surface with fine irregularities. The dielectric layer is preferably a film composed of an oxide of the valve-action metal. In the case where, for example, an aluminum foil is used as a valve-acting metal substrate, a dielectric layer that is an oxide film may be formed by subjecting the surface of the aluminum foil to an anodic oxidation treatment (i.e., chemical conversion) in an aqueous solution containing ammonium adipate or the like. It is preferable that the dielectric layer be not formed on the surface of the core part.

Examples of the material constituting the insulating layer included in the solid electrolytic capacitor according to the present invention include insulative resins, such as a polyphenylsulfone resin, a polyethersulfone resin, a cyanate ester resin, a fluororesin (e.g., tetrafluoroethylene or a tetrafluoroethylene-perfluoroalkyl vinyl ether copolymer), a polyimide resin, and a polyamide imide resin and derivatives and precursors of the above insulative resins. The insulating layer may be composed of the same material as the sealing resin described below.

Examples of the material constituting the solid electrolyte layer included in the solid electrolytic capacitor according to the present invention include conductive high-molecular compounds, such as polypyrroles, polythiophenes, and polyanilines. Among the above compounds, polythiophenes are preferable and poly(3,4-ethylenedioxythiophene), that is, "PEDOT", is particularly preferable. The above conductive high-molecular compounds may include a dopant, such as polystyrene sulfonic acid (PSS). The solid electrolyte layer preferably includes an inner layer that fills the pores (recesses) of the dielectric layer and an outer layer that covers the dielectric layer.

The conductive layer included in the solid electrolytic capacitor according to the present invention preferably includes a carbon layer that serves as a backing and a silver layer disposed on the carbon layer. The conductive layer may include only a carbon layer or a silver layer. The conductive layers, such as a carbon layer and a silver layer, are preferably arranged to cover the entire surface of the solid electrolyte layer.

Examples of the material constituting the sealing resin included in the solid electrolytic capacitor according to the present invention include an epoxy resin and a phenol resin.

The solid electrolytic capacitor **1** illustrated in FIG. **1(a)** is preferably produced by the following method.

As shown in FIG. **2-1(a)**, a valve-acting metal substrate **11** that includes a core part **11b** and a porous part **11a**, such as an etched layer, disposed on the entirety of a principal surface of the core part **11b** is prepared (or obtained). A dielectric layer **12** is formed in the surface of the porous part **11a** as illustrated in FIG. **2-1(b)**. As described above, in the case where, for example, an aluminum foil is used as a valve-acting metal substrate, a dielectric layer that is an oxide film may be formed by subjecting the surface of the aluminum foil to an anodic oxidation treatment (i.e., chemical conversion) in an aqueous solution containing ammonium adipate or the like.

A portion of the dielectric layer **12** and a portion of the porous part **11a** are removed with a laser or the like such that the core part **11b**, which serves as an anode part, is exposed as illustrated in FIG. **2-1(c)**. In this case, the surface of the core part **11b** is at a lower level than the surface of the porous part **11a**. In FIG. **2-1(c)**, a portion of the core part **11b** which acts as the peripheral portion of the valve-acting metal substrate **11** is exposed. Alternatively, the dielectric layer **12** may be formed after the core part **11b** has been exposed by removing a portion of the porous part **11a**. In such a case, it is preferable to form a mask on the surface of the core part **11b** in order to prevent the dielectric layer **12** from being formed in the surface of the core part **11b**.

In another case, in order to increase the production efficiency, a foil that has been subjected to chemical conversion, that is, a chemically converted foil, may be used as a valve-acting metal substrate provided with a dielectric layer formed in the surface of the metal base. In such a case, since the dielectric layer is disposed on the entirety of the chemically converted foil, the core part, which serves as an anode part, may be exposed by removing a portion of the dielectric layer and a portion of the porous part with a laser or the like.

An insulating layer **15** is formed on the core part **11b** by applying an insulative resin to the core part **11b** as illustrated in FIG. **2-1(d)**. The method for applying the insulative resin is not limited. For example, a method in which a dispenser is used and screen printing may be used.

A solid electrolyte layer **13** is formed on the dielectric layer **12** as illustrated in FIG. **2-1(e)**. The solid electrolyte layer may be formed by, for example, forming a polymer film composed of poly(3,4-ethylenedioxythiophene) or the like on the surface of the dielectric layer using a coating liquid containing a monomer such as 3,4-ethylenedioxythiophene or by applying a dispersion containing a polymer such as poly(3,4-ethylenedioxythiophene) onto the surface of the dielectric layer and drying the resulting coating film. It is preferable to form the solid electrolyte layer by forming an inner layer that fills the pores (recesses) of the dielectric layer and subsequently forming an outer layer that covers the dielectric layer.

A conductive layer **14** is formed on the solid electrolyte layer **13** as illustrated in FIG. **2-1(f)**. It is preferable to form the conductive layer by forming a carbon layer and a silver layer successively. Alternatively, only a carbon layer may be formed. In another case, only a silver layer may be formed. The carbon layer and the silver layer may be formed by, for example, applying a carbon paste drying the resulting coating film, subsequently applying the silver paste, and drying the resulting coating film.

Bump electrodes (paste electrodes) **31'** are formed on the conductive layer **14** using a conductive paste as illustrated in FIG. **2-2(g)**. Subsequently, a sealing resin **20** is disposed on the conductive layer **14** and the insulating layer **15** as illustrated in FIG. **2-2(h)** in order to perform sealing with the sealing resin **20** such that the bump electrodes **31'** are completely covered with the sealing resin **20**. The sealing resin may be formed by resin molding or the like. Subsequently, the sealing resin **20** is trimmed such that the surfaces of the bump electrodes **31'** are exposed as illustrated in FIG. **2-2(i)**. Thus, cathodic via electrodes **31** are formed in the sealing resin **20** disposed on the conductive layer **14** so as to penetrate the sealing resin **20**. Note that, the cathodic via electrodes **31** are substantially the same as the bump electrodes **31'**.

Via holes **45** are formed in the insulating layer **15** and the sealing resin **20** that are disposed on and above the core part **11b** with a laser or the like so as to penetrate the insulating layer **15** and the sealing resin **20** as illustrated in FIG. **2-2(j)**. Subsequently, as illustrated in FIG. **2-2(k)**, first anodic via electrodes **41** are formed in the sealing resin **20** disposed on the insulating layer **15** so as to penetrate the sealing resin **20**, and second anodic via electrodes **42** (not illustrated) are formed in the insulating layer **15** disposed on the core part **11b** so as to penetrate the insulating layer **15**. The first anodic via electrodes may be, for example, plated electrodes or paste electrodes. The second anodic via electrodes may be, for example, plated electrodes or paste electrodes.

A cathodic outer electrode **30** electrically connected to the conductive layer **14** through the cathodic via electrodes **31** and an anodic outer electrode **40** electrically connected to the core part **11b** through the second anodic via electrodes **42** and the first anodic via electrodes **41** are formed as illustrated in FIG. **2-2(l)**. The anodic outer electrode may be, for example, a metal electrode, a paste electrode, or a ball-like terminal. The cathodic outer electrode may be, for example, a metal electrode, a paste electrode, or a ball-like terminal.

The solid electrolytic capacitor **1** illustrated in FIG. **1(a)** is preferably produced by the above-described method.

Second Embodiment

In the second embodiment of the present invention, the sealing resin and the anodic outer electrode are disposed on and above the core part in this order; a first anodic via electrode is formed in the sealing resin disposed on the core part; the first anodic via electrode is arranged to come into direct contact with the core part; and the core part is electrically drawn to the surface of the sealing resin through the first anodic via electrode. In the structure according to the second embodiment of the present invention, the core part is arranged substantially close to the anodic outer electrode and the length of the via electrodes having a narrow conductive path may be relatively reduced accordingly. This makes it possible to reduce the overall resistance of the capacitor and pass a large current through the capacitor. In particular, in the case where a three-terminal capacitor is used as a circuit by-pass capacitor, the structure in which the proportion of the conductor in the conductive path is high as in the second embodiment may be advantageous, because it is desirable to maximize the current-carrying capacity between anodes.

In addition, as in the first embodiment, the sealing resin and the cathodic outer electrode are disposed on the conductive layer, which serves as a cathode part, in this order, a cathodic via electrode is formed in the sealing resin

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disposed on the conductive layer, and the cathode part is electrically drawn to the surface of the sealing resin through the cathodic via electrode.

The solid electrolytic capacitor **2** illustrated in FIG. **3(a)** includes a capacitor element **10'**, a sealing resin **20**, a cathodic outer electrode **30**, and an anodic outer electrode **40**. As illustrated in FIGS. **3(a)** and **3(b)**, the capacitor element **10'** includes a valve-acting metal substrate **11** including a core part **11b** and a porous part **11a** disposed on a principal surface of the core part **11b**, a dielectric layer **12** formed in the surface of the porous part **11a**, a solid electrolyte layer **13** disposed on the dielectric layer **12**, and a conductive layer **14** disposed on the solid electrolyte layer **13**. An insulating layer **15** is disposed on a principal surface of the valve-acting metal substrate **11** as illustrated in FIG. **3(a)**.

The solid electrolytic capacitor **2** illustrated in FIG. **3(a)** includes a capacitor element **10'**, a sealing resin **20**, a cathodic outer electrode **30**, and an anodic outer electrode **40**. As illustrated in FIGS. **3(a)** and **3(b)**, the capacitor element **10'** includes a valve-acting metal substrate **11** including a core part **11b** and a porous part **11a** disposed on a principal surface of the core part **11b**, a dielectric layer **12** formed in the surface of the porous part **11a**, a solid electrolyte layer **13** disposed on the dielectric layer **12**, and a conductive layer **14** disposed on the solid electrolyte layer **13**. An insulating layer **15** is disposed on a principal surface of the valve-acting metal substrate **11** and surrounds the outer periphery of the dielectric layer **12**, the solid electrolyte layer **13** and the conductive layer **14** and the as illustrated in FIG. **3(a)**. While not shown in FIG. **3(c)**, the insulating layer **15** preferably extends around the entire periphery of the insulating layer **14** as viewed in FIG. **3(c)**.

In the solid electrolytic capacitor **2** illustrated in FIG. **3(a)**, core part **11b** has a recess in which the porous part **11a** is located. This is shown more clearly in FIGS. **3(b)** and **3(c)**. It is preferable that the porous part **11a** be disposed at the center of the valve-acting metal substrate **11** and the core part **11b** be disposed both below the core part **11b** and laterally outward of (peripherally of) the core part **11b** as illustrated in FIGS. **3(b)** and **3(c)**. It is also preferable that the insulating layer **15** be disposed on the inner walls of the recess between the porous part **11a** and the outer edges of the dielectric **12**, the solid electrolyte layer **13** and the conductive layer **14**. While the foregoing structure is preferred, the recess need not be formed in the valve-acting metal substrate **11**, and the surface of the core part **11b** may be at the same level as the surface of the porous part **11a** or at a lower level than the surface of the porous part **11a** on the principal surface of the valve-acting metal substrate **11**.

A principal surface of the capacitor element **10'** is sealed with the sealing resin **20**. In the solid electrolytic capacitor **2** illustrated in FIG. **3(a)**, the sealing resin **20** is disposed on the conductive layer **14** and the core part **11b** so as to cover the principal surface of the capacitor element **10'**.

The cathodic outer electrode **30** is electrically connected to the conductive layer **14**. In the solid electrolytic capacitor **2** illustrated in FIG. **3(a)**, the sealing resin **20** and the cathodic outer electrode **30** are disposed on and above the conductive layer **14** in this order, and cathodic via electrodes **31** are formed in the sealing resin **20** disposed on the conductive layer **14** so as to penetrate the sealing resin **20**. The conductive layer **14** (a cathode part **21**) is electrically drawn to the surface of the sealing resin **20** through the cathodic via electrodes **31**. The cathodic via electrodes **31** exposed at the surface of the sealing resin **20** are connected to the cathodic outer electrode **30**.

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The form, cross-sectional shape, etc. of the cathodic via electrodes **31** are preferably the same as in the first embodiment. The form, shape, etc. of the cathodic outer electrode **30** are also the same as in the first embodiment.

The anodic outer electrode **40** is electrically connected to the core part **11b**. In the solid electrolytic capacitor **2** illustrated in FIG. **3(a)**, the sealing resin **20** and the anodic outer electrode **40** are to be disposed on and above the core part **11b** in this order. A first anodic via electrode **41** is formed in the sealing resin **20** disposed on the core part **11b** so as to penetrate the sealing resin **20**. The first anodic via electrode **41** is arranged to come into direct contact with the core part **11b**. The core part **11b** (an anode part **22**) is electrically drawn to the surface of the sealing resin **20** through the first anodic via electrode **41**. The first anodic via electrode **41** exposed at the surface of the sealing resin **20** is connected to the anodic outer electrode **40**.

The form, cross-sectional shape, etc. of the first anodic via electrode **41** are the same as in the first embodiment. The form, shape, etc. of the anodic outer electrode **40** are also the same as in the first embodiment.

In FIG. **3(a)**, the cathodic outer electrode **30** and the anodic outer electrode **40** are arranged not to come into contact with each other and are insulated from each other on the surface of the sealing resin **20**.

Various modifications are possible. For example, a surface of the solid electrolytic capacitor **2** which is other than the surface that includes the anodic outer electrode **40** and the cathodic outer electrode **30** may be covered with another insulating layer in order to protect the other surface. Moreover, a stress relaxation layer, a damp-proof membrane, and the like may optionally be interposed between the capacitor element and the sealing resin in order to protect the capacitor element.

The material constituting the valve-acting metal substrate included in the capacitor element, etc. are the same as in the first embodiment. The thickness of the core part is preferably 5 μm or more and 300 μm or less. The thickness of the porous part (the thickness of one porous part except the core part) is preferably 5 μm or more and 200 μm or less. In the case where a recess is formed in the valve-acting metal substrate, the depth of the recess is preferably 5 μm or more and 200 μm or less.

The materials constituting the dielectric layer, the solid electrolyte layer, the conductive layer, the insulating layer, and the sealing resin that are included in the capacitor element, etc. are the same as in the first embodiment. In the case where the porous part is disposed in the recess of the valve-acting metal substrate, it is preferable that the solid electrolyte layer and the conductive layer be not protruded from the recess.

The solid electrolytic capacitor **2** illustrated in FIG. **3(a)** is preferably produced by the following method.

FIGS. **4-1(a)** through **4-2(k)** are schematic perspective views illustrating an example of the method for producing the solid electrolytic capacitor **2** illustrated in FIG. **3(a)**.

As illustrated in FIG. **4-1(a)**, a recess **11'** is formed in a valve-acting metal substrate **11** including a core part **11b**, and a porous part **11a**, such as an etched layer, is formed in the inner surface of the recess **11'**. The recess may be formed by any method. For example, cutting, pressing, and etching may be used. The recess **11'** and the porous part **11a** may be simultaneously formed by etching. In FIG. **4-1(a)**, the core part **11b** that surrounds the recess **11'** and acts the peripheral portion of the valve-acting metal substrate **11** serves as an anode part. In this case, the surface of the core part **11b** is at a higher level than the surface of the porous part **11a**.

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An insulating layer **15** is formed on the peripheral portion of the recess **11'**, which comes into contact with the core part **11b**, by applying an insulative resin to the peripheral portion of the recess **11'** as illustrated in FIG. 4-1(b). The method for applying the insulative resin is not limited. For example, a method in which a dispenser is used and screen printing may be used. Alternatively, the porous part **11a** may be formed in the inner surface of the recess **11'** after the insulating layer **15** has been formed on the peripheral portion of the recess **11'**.

A dielectric layer **12** is formed in the surface of the porous part **11a** as illustrated in FIG. 4-1(c). It is preferable to form a mask on the surface of the core part **11b** in order to prevent the dielectric layer **12** from being formed in the surface of the core part **11b**.

A solid electrolyte layer **13** is formed on the dielectric layer **12** as illustrated in FIG. 4-1(d). It is preferable to form the solid electrolyte layer by forming an inner layer that fills the pores of the dielectric layer and subsequently forming an outer layer that covers the dielectric layer.

A conductive layer **14** is formed on the solid electrolyte layer **13** as illustrated in FIG. 4-1(e). It is preferable to form the conductive layer by forming a carbon layer and a silver layer successively. Alternatively, only a carbon layer may be formed. In another case, only a silver layer may be formed.

Bump electrodes (paste electrodes) **31'** are formed on the conductive layer **14** using a conductive paste as illustrated in FIG. 4-2(f). Subsequently, a sealing resin **20** is disposed on the core part **11b**, the conductive layer **14**, and the insulating layer **15** as illustrated in FIG. 4-2(g) in order to perform sealing with the sealing resin **20** such that the bump electrodes **31'** are completely covered with the sealing resin **20**. The sealing resin may be formed by resin molding or the like. Subsequently, the sealing resin **20** is trimmed such that the surfaces of the bump electrodes **31'** are exposed as illustrated in FIG. 4-2(h). Thus, cathodic via electrodes **31** are formed in the sealing resin **20** disposed on the conductive layer **14** so as to penetrate the sealing resin **20**. The cathodic via electrodes **31** are substantially the same as the bump electrodes **31'**.

Via holes **45** are formed in the sealing resin **20** disposed on the core part **11b** with a laser or the like so as to penetrate the sealing resin **20** as illustrated in FIG. 4-2(i). Subsequently, first anodic via electrodes **41** are formed in the sealing resin **20** disposed on the core part **11b** so as to penetrate the sealing resin **20** as illustrated in FIG. 4-2(j). The first anodic via electrodes may be, for example, plated electrodes or paste electrodes.

A cathodic outer electrode **30** electrically connected to the conductive layer **14** through the cathodic via electrodes **31** and an anodic outer electrode **40** electrically connected to the core part **11b** through the first anodic via electrodes **41** are formed as illustrated in FIG. 4-2(k). The anodic outer electrode may be, for example, a metal electrode, a paste electrode, or a ball-like terminal. The cathodic outer electrode may be, for example, a metal electrode, a paste electrode, or a ball-like terminal.

The solid electrolytic capacitor **2** illustrated in FIG. 3(a) is produced by the above-described method.

OTHER EMBODIMENTS

The solid electrolytic capacitor according to the present invention is not limited to the above-described embodiments. Variations and modifications may be made to the structure, production conditions, etc. of the solid electrolytic capacitor within the scope of the present invention.

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In particular, the method for electrically connecting the conductive layer to the cathodic outer electrode is not limited to the methods described in the first and second embodiments. Although the conductive layer (the cathode part **21**) is electrically drawn to the surface of the sealing resin **20** through the cathodic via electrodes **31** in the solid electrolytic capacitors **1** and **2** illustrated in FIGS. 1(a) and 3(a), respectively, the solid electrolytic capacitor according to the present invention does not necessarily include the cathodic via electrode. Alternatively, for example, a lead frame may be connected to the conductive layer.

In the solid electrolytic capacitor according to the present invention, the number of the anode terminals can be varied and one, two or more anode terminals may be provided as described in the first embodiment. Similarly, the number of the cathode terminals can be varied and one, two or more cathode terminals can be provided.

REFERENCE SIGNS LIST

- 1, 2** SOLID ELECTROLYTIC CAPACITOR
- 10, 10'** CAPACITOR ELEMENT
- 11** VALVE-ACTING METAL SUBSTRATE
- 11'** RECESS
- 11a** POROUS PART
- 11b** CORE PART
- 12** DIELECTRIC LAYER
- 13** SOLID ELECTROLYTE LAYER
- 14** CONDUCTIVE LAYER
- 15** INSULATING LAYER
- 20** SEALING RESIN
- 21** CATHODE PART
- 22** ANODE PART
- 30** CATHODIC OUTER ELECTRODE
- 31** CATHODIC VIA ELECTRODE
- 31'** BUMP ELECTRODE
- 40** ANODIC OUTER ELECTRODE
- 41** FIRST ANODIC VIA ELECTRODE
- 42** SECOND ANODIC VIA ELECTRODE
- 45** VIA HOLE

The invention claimed is:

1. A solid electrolytic capacitor comprising:
 - a capacitor element including a valve-acting metal substrate including a core part and a porous part located above and disposed on at least one principal surface of the core part, a dielectric layer located above and disposed on a surface of the porous part, a solid electrolyte layer located above and disposed on a surface of the dielectric layer, and a conductive layer located above and disposed on a surface of the solid electrolyte layer;
 - a sealing resin located above the conductive layer which seals a principal surface of the capacitor element;
 - a cathodic outer electrode located above the sealing resin and electrically connected to the conductive layer; and
 - an anodic outer electrode located above the sealing resin and electrically connected to the core part;
 - an anodic via electrode penetrating the sealing resin at a location over the core part and coming into contact with the core part without penetrating the porous part so that the core part is electrically drawn to a surface of the sealing resin through the anodic via electrode, the anodic via electrode being exposed at the surface of the sealing resin and being connected to the anodic outer electrode at the exposed surface.

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2. The solid electrolytic capacitor according to claim 1, wherein an upper surface of the core part is at the same level or above an upper surface of the porous part.

3. The solid electrolytic capacitor according to claim 1, wherein the anodic via electrode is a plated electrode.

4. The solid electrolytic capacitor according to claim 1, wherein the first anodic via electrode is a paste electrode including a material formed by curing a conductive paste.

5. The solid electrolytic capacitor according to claim 1, wherein the anodic via electrode has a reversely tapered cross-sectional shape, the width of the reversely tapered cross-sectional shape increasing in the direction from the core part toward the anodic outer electrode.

6. The solid electrolytic capacitor according to claim 1, wherein the anodic via electrode is a columnar metal pin.

7. A solid electrolytic capacitor comprising:

(a) a valve-acting metal substrate including:

(i) a core part having a centrally located cathode section and an anode section located laterally outward of the cathode section;

(ii) a porous part located above and extending over the cathode section but not extending over the anode section such that the cathode section of the core part is covered by the porous part but the anode section of the core part is not covered by the porous part;

(b) a dielectric layer located above and extending over the porous part;

(c) a solid electrolyte layer located above and extending over the dielectric layer;

(d) a conductive layer located above and extending over the solid electrolyte layer;

(e) an insulating layer located above and extending over the anode section of the core part;

(f) a sealing resin located above and extending over both the insulating and conductive layers;

(g) an anodic outer electrode located above and extending over the sealing resin and being electrically connected to the core part of the valve action metal substrate by a first anodic via electrode which extends through a portion of the sealing resin and a second anodic via electrode which extends through the insulating layer; and

(h) a cathodic outer electrode located above and extending over the sealing resin and being electrically connected to the conductive layer.

8. The solid electrolytic capacitor according to claim 7, wherein the first and second anodic via electrodes are plated electrodes.

9. The solid electrolytic capacitor according to claim 7, wherein the first and second anodic via electrodes are paste electrodes including a material formed by curing a conductive paste.

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10. The solid electrolytic capacitor according to claim 7, wherein each of the first and second anodic via electrodes has a reversely tapered cross-sectional shape which increases in the direction from the core part toward the anodic outer electrode.

11. The solid electrolytic capacitor according to claim 7, wherein the first and second anodic via electrodes are columnar metal pins.

12. The solid electrolytic capacitor according to claim 7, wherein the insulating layer is composed of the same material as the sealing resin.

13. The solid electrolytic capacitor according to claim 7, wherein the anodic outer electrode and the cathodic outer electrode are metal electrodes including a metal film.

14. The solid electrolytic capacitor according to claim 7, wherein the anodic outer electrode and the cathodic outer electrode are paste electrodes including a material formed by curing a conductive paste.

15. The solid electrolytic capacitor according to claim 7, wherein a surface of the solid electrolytic capacitor, the surface being other than a surface that includes the anodic outer electrode and the cathodic outer electrode, is covered with another insulating layer.

16. The solid electrolytic capacitor according to claim 7, wherein a stress relaxation layer is interposed between the conductive layer and the sealing resin.

17. The solid electrolytic capacitor according to claim 7, wherein a damp-proof membrane is interposed between the conductive layer and the sealing resin.

18. The solid electrolytic capacitor according to claim 7, wherein the insulating layer is located on an upper surface of the core part of the valve-action metal substrate.

19. The solid electrolytic capacitor according to claim 7, wherein the first anodic via electrode is located above and extends over the anode section of the core part and the second anodic via electrode is located above and extends over the anode section of the core part.

20. The solid electrolytic capacitor according to claim 19, wherein the first anodic via electrode extends from the anodic outer electrode to the second anodic via electrode and the second anodic via electrode extends from the first anodic via electrode to the anode section of the core part.

21. The solid electrolytic capacitor according to claim 7, wherein the anode section of the core part surrounds the centrally located cathode section.

22. The solid electrolytic capacitor according to claim 7, wherein the capacitor is a planar capacitor which lies in a plane and the core part, the dielectric layer, the solid electrolyte layer and the insulating layers all lie in respective planes lying parallel to the plane of the capacitor.

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